# PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE:      | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |

### **CONVEYING PARTY DATA**

| Name                 | Execution Date |
|----------------------|----------------|
| GLOBALFOUNDRIES INC. | 05/15/2020     |

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| State/Country:  | TAIWAN                                       |
| Postal Code:    | 300-78                                       |

## **PROPERTY NUMBERS Total: 28**

| Property Type  | Number   |
|----------------|----------|
| Patent Number: | 8703620  |
| Patent Number: | 10262099 |
| Patent Number: | 10217633 |
| Patent Number: | 10198550 |
| Patent Number: | 10402524 |
| Patent Number: | 10261109 |
| Patent Number: | 10332745 |
| Patent Number: | 10248754 |
| Patent Number: | 10431732 |
| Patent Number: | 10235492 |
| Patent Number: | 10325824 |
| Patent Number: | 10354045 |
| Patent Number: | 10199261 |
| Patent Number: | 10297546 |
| Patent Number: | 10192791 |
| Patent Number: | 10372871 |
| Patent Number: | 10199271 |
| Patent Number: | 10276461 |
| Patent Number: | 10311201 |
| Patent Number: | 10229850 |
|                |          |

PATENT REEL: 054452 FRAME: 0776

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| Property Type  | Number   |
|----------------|----------|
| Patent Number: | 10276374 |
| Patent Number: | 10401837 |
| Patent Number: | 10386726 |
| Patent Number: | 10386715 |
| Patent Number: | 10401724 |
| Patent Number: | 10373942 |
| Patent Number: | 10423078 |
| Patent Number: | 10324381 |

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| ATTORNEY DOCKET NUMBER: | 0941-4477M      |
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| DATE SIGNED:            | 11/17/2020      |

#### **Total Attachments: 50**

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## Patent Assignment and Reservation

For good and valuable consideration, the receipt of which is hereby acknowledged, and subject to the reservations stated in the Patent Assignment Agreement Reference No. PA20200002 between the parties with an Effective Date of March 31, 2020, GLOBALFOUNDRIES Inc., a Cayman Islands corporation, GLOBALFOUNDRIES Dresden Module One LLC & CO. KG, a German corporation, and GLOBALFOUNDRIES SINGAPORE PTE. LTD. (hereinafter collectively "ASSIGNOR"), hereby confirm their grant and assignment on April 10, 2020 to TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED, an entity organized under the laws of the Republic of China ("BUYER"), a corporation having a place of business at Hsinchu, Taiwan (hereinafter "ASSIGNEE"), all of ASSIGNOR's right, title and interest in and to (a) the United States Letters Patents identified in the attached Exhibit A, (b) the non-United States Letters Patents identified in Exhibit B, (c) the United States and non-United States patent applications identified in the attached Exhibit C ("Assigned Patent Applications"), (d) patents issuing from the Assigned Patent Applications, and (e) patents that may reissue from any of the foregoing, (hereinafter, collectively, "ASSIGNED PATENTS"), to have and to hold the same, unto ASSIGNEE for its own use and enjoyment and for the use and enjoyment of its successors and assigns, including but not limited to the right to sue for injunctive relief and all damages for infringement of any of the Assigned Patents accruing on and after the Assignment Date and the right to sue therefore under such Assigned Patents, for the full term or terms of all such ASSIGNED PATENTS, subject to all rights granted under the ASSIGNED PATENTS to third parties prior to said Assignment.

ASSIGNOR hereby reserves and retains, for the benefit of itself and its subsidiaries and its and their successors and assigns, the rights and licenses set forth in the Patent Assignment Agreement between the parties.

IN WITNESS WHEREOF, ASSIGNOR has caused this Patent Assignment and Reservation to be duly signed on its behalf.

GLOBALFOUNDRIES INC.
GLOBALFOUNDRIES Dresden Module One LLC & CO. KG
GLOBALFOUNDRIES SINGAPORE, PTE. LTD.

Signature: 27. M.L.

]

Date: May 15, 2020

Name: Adam P. Noah

Title: VP and Chief IP Counsel, GLOBALFOUNDRIES US Inc.

## **EXHIBIT A**

# **LISTED PATENTS (United States)**

| Document   | App Serial |            |                   | Selected |  |
|------------|------------|------------|-------------------|----------|--|
| No.        | No.        | File Date  | <b>Grant Date</b> | Patent   | Title  |
| US10008597 | 14/505536  | 10/3/2014  | 6/26/2018         | 540      | Semiconductor devices with asymmetric halo implantation and method of manufacture                          |
| US10062762 | 14/581857  | 12/23/2014 | 8/28/2018         | 541      | Semiconductor devices having low contact resistance and low current leakage                                |
| US10066303 | 14/634535  | 2/27/2015  | 9/4/2018          | 542      | Thin NiB or CoB capping layer for non-<br>noble metallic bonding landing pads                              |
| US10091909 | 14/632180  | 2/26/2015  | 10/2/2018         | 543      | Method and device for cooling a heat generating component  |
| US10109516 | 15/164204  | 5/25/2016  | 10/23/2018        | 544      | Overhead substrate handling and storage system   |
| US10134903 | 15/343021  | 11/3/2016  | 11/20/2018        | 545      | Vertical slit transistor with optimized AC performance   |
| US10168612 | 15/375623  | 12/12/2016 | 1/1/2019          | 546      | Photomask blank including a thin chromium hardmask   |
| US10170553 | 15/626241  | 6/19/2017  | 1/1/2019          | 547      | Shaped terminals for a bipolar junction transistor   |
| US10191112 | 15/355256  | 11/18/2016 | 1/29/2019         | 548      | Early development of a database of fail signatures for systematic defects in integrated circuit (IC) chips |
| US10192748 | 15/297848  | 10/19/2016 | 1/29/2019         | 549      | Controlling of etch depth in deep via etching processes and resultant structures                           |
| US10192791 | 15/913547  | 3/6/2018   | 1/29/2019         | 550      | Semiconductor devices with robust low-<br>k sidewall spacers and method for<br>producing the same          |
| US10192822 | 14/623115  | 2/16/2015  | 1/29/2019         | 551      | Modified tungsten silicon  |
| US10198550 | 15/478377  | 4/4/2017   | 2/5/2019          | 552      | SRAF insertion with artificial neural network  |
| US10199261 | 15/653638  | 7/19/2017  | 2/5/2019          | 553      | Via and skip via structures  |
| US10199271 | 15/693651  | 9/1/2017   | 2/5/2019          | 554      | Self-aligned metal wire on contact structure and method for forming same                                   |
| US10217633 | 15/456757  | 3/13/2017  | 2/26/2019         | 555      | Substantially defect-free polysilicon gate arrays  |
| US10229850 | 15/860231  | 1/2/2018   | 3/12/2019         | 556      | Cut-first approach with self-alignment during line patterning  |

| US10229918 | 15/662594 | 7/28/2017  | 3/12/2019 | 557 | Methods of forming semiconductor devices using semi-bidirectional patterning                                       |
|------------|-----------|------------|-----------|-----|--|
| US10235492 | 15/617403 | 6/8/2017   | 3/19/2019 | 558 | Matching IC design patterns using weighted XOR density   |
| US10241502 | 15/374453 | 12/9/2016  | 3/26/2019 | 559 | Methods of error detection in fabrication processes  |
| US10243047 | 15/372929 | 12/8/2016  | 3/26/2019 | 560 | Active and passive components with deep trench isolation structures  |
| US10245667 | 15/654130 | 7/19/2017  | 4/2/2019  | 561 | Chip joining by induction heating  |
| US10248754 | 15/602810 | 5/23/2017  | 4/2/2019  | 562 | Multi-stage pattern recognition in circuit designs   |
| US10256126 | 15/272924 | 9/22/2016  | 4/9/2019  | 563 | Gas flow process control system and method using crystal microbalance(s)   |
| US10261109 | 15/597202 | 5/17/2017  | 4/16/2019 | 564 | Probe card support insert, container, system and method for storing and transporting one or more probe cards       |
| US10262099 | 15/444899 | 2/28/2017  | 4/16/2019 | 565 | Methodology for model-based self-<br>aligned via awareness in optical<br>proximity correction                      |
| US10262905 | 14/867797 | 9/28/2015  | 4/16/2019 | 566 | Simplified multi-threshold voltage scheme for fully depleted SOI MOSFETs   |
| US10276374 | 15/709730 | 9/20/2017  | 4/30/2019 | 567 | Methods for forming fins   |
| US10276390 | 15/097861 | 4/13/2016  | 4/30/2019 | 568 | Method and apparatus for reducing threshold voltage mismatch in an integrated circuit                              |
| US10276461 | 15/665974 | 8/1/2017   | 4/30/2019 | 569 | Split probe pad structure and method   |
| US10278306 | 14/632194 | 2/26/2015  | 4/30/2019 |     | Method and device for cooling a heat generating component  |
| US10283407 | 15/817554 | 11/20/2017 | 5/7/2019  |     | Two-dimensional self-aligned super via integration on self-aligned gate contact                                    |
| US10283423 | 15/292184 | 10/13/2016 | 5/7/2019  | 570 | Test structure macro for monitoring dimensions of deep trench isolation regions and local trench isolation regions |
| US10289109 | 15/258217 | 9/7/2016   | 5/14/2019 | 571 | Methods of error detection in fabrication processes  |
| US10297546 | 15/652594 | 7/18/2017  | 5/21/2019 | 572 | Interconnect structures for a security application   |
| US10302414 | 14/852897 | 9/14/2015  | 5/28/2019 | 573 | Scatterometry method and system  |
| US10311186 | 15/096551 | 4/12/2016  | 6/4/2019  | 574 | Three-dimensional pattern risk scoring   |

| US10311201 | 15/670158 | 8/7/2017   | 6/4/2019  | 575 | Alignment key design rule check for correct placement of abutting cells in an integrated circuit                                |
|------------|-----------|------------|-----------|-----|---|
| US10322493 | 15/046496 | 2/18/2016  | 6/18/2019 | 576 | Chemical mechanical polishing apparatus   |
| US10324381 | 16/159877 | 10/15/2018 | 6/18/2019 | 577 | FinFET cut isolation opening revision to compensate for overlay inaccuracy  |
| US10325808 | 15/858691 | 12/29/2017 | 6/18/2019 |     | Crack prevent and stop for thin glass substrates  |
| US10325824 | 15/622061 | 6/13/2017  | 6/18/2019 | 578 | Methods, apparatus and system for threshold voltage control in FinFET devices   |
| US10325862 | 15/657666 | 7/24/2017  | 6/18/2019 | 579 | Wafer rigidity with reinforcement structure   |
| US10331844 | 15/290569 | 10/11/2016 | 6/25/2019 | 580 | Methods of tuning current ratio in a current mirror for transistors formed with the same FEOL layout and a modified BEOL layout |
| US10332745 | 15/597277 | 5/17/2017  | 6/25/2019 | 581 | Dummy assist features for pattern support   |
| US10345694 | 15/658721 | 7/25/2017  | 7/9/2019  | 582 | Model-based generation of dummy features  |
| US10347740 | 15/367366 | 12/2/2016  | 7/9/2019  | 583 | Fin structures and multi-Vt scheme based on tapered fin and method to form  |
| US10354045 | 15/624764 | 6/16/2017  | 7/16/2019 | 584 | Modeling 3D physical connectivity into planar 2D domain to identify via redundancy  |
| US10355020 | 15/180860 | 6/13/2016  | 7/16/2019 | 585 | FinFETs having strained channels, and methods of fabricating finFETs having strained channels                                   |
| US10372871 | 15/662419 | 7/28/2017  | 8/6/2019  | 586 | IC layout post-decomposition mask allocation optimization   |
| US10373942 | 15/829459 | 12/1/2017  | 8/6/2019  | 587 | Logic layout with reduced area and method of making the same  |
| US10379191 | 15/868248 | 1/11/2018  | 8/13/2019 | 588 | Apparatus and method for vector s-<br>parameter measurements  |
| US10381339 | 15/927422 | 3/21/2018  | 8/13/2019 | 589 | Integrated circuits with memory cell test circuits and methods for producing the same   |
| US10381826 | 15/135585 | 4/22/2016  | 8/13/2019 | 590 | Integrated circuit electrostatic discharge protection   |
| US10386714 | 15/401299 | 1/9/2017   | 8/20/2019 | 591 | Creating knowledge base for optical proximity correction to reduce subresolution assist feature printing                        |

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| US10386715 | 15/730830 | 10/12/2017 | 8/20/2019  | 592 | Methodology for post-integration awareness in optical proximity correction   |
|------------|-----------|------------|------------|-----|--|
| US10386726 | 15/720182 | 9/29/2017  | 8/20/2019  | 593 | Geometry vectorization for mask process correction   |
| US10395955 | 15/432925 | 2/15/2017  | 8/27/2019  | 594 | Method and system for detecting a coolant leak in a dry process chamber wafer chuck                                |
| US10396000 | 14/789476 | 7/1/2015   | 8/27/2019  |     | Test structure macro for monitoring dimensions of deep trench isolation regions and local trench isolation regions |
| US10401724 | 15/805179 | 11/7/2017  | 9/3/2019   | 595 | Pellicle replacement in EUV mask flow  |
| US10401837 | 15/719680 | 9/29/2017  | 9/3/2019   | 596 | Generating risk inventory and common process window for adjustment of manufacturing tool                           |
| US10402524 | 15/588984 | 5/8/2017   | 9/3/2019   | 597 | Prediction of process-sensitive geometries with machine learning   |
| US10423078 | 16/398841 | 4/30/2019  | 9/24/2019  |     | FinFET cut isolation opening revision to compensate for overlay inaccuracy   |
| US10431732 | 15/609621 | 5/31/2017  | 10/1/2019  | 598 | Shielded magnetoresistive random access memory devices and methods for fabricating the same                        |
| US10460067 | 15/791210 | 10/23/2017 | 10/29/2019 | 599 | Method of patterning target layer  |
| US6258659  | 09/725412 | 11/29/2000 | 7/10/2001  | 1   | Embedded vertical DRAM cells and dual workfunction logic gates   |
| US6335152  | 09/564408 | 5/1/2000   | 1/1/2002   | 2   | Use of RTA furnace for photoresist baking  |
| US6342414  | 09/734189 | 12/12/2000 | 1/29/2002  | 3   | Damascene NiSi metal gate high-k transistor  |
| US6372635  | 09/776736 | 2/6/2001   | 4/16/2002  | 4   | Method for making a slot via filled dual damascene low k interconnect structure without middle stop layer          |
| US6376343  | 09/812695 | 3/21/2001  | 4/23/2002  | 5   | Reduction of metal silicide/silicon interface roughness by dopant implantation processing                          |
| US6392432  | 09/602859 | 6/26/2000  | 5/21/2002  | 6   | Automated protection of IC devices from EOS (electro over stress) damage due to an undesired DC transient          |
| US6461878  | 09/614666 | 7/12/2000  | 10/8/2002  | 7   | Feedback control of strip time to reduce post strip critical dimension variation in a transistor gate electrode    |
| US6475874  | 09/731031 | 12/7/2000  | 11/5/2002  | 8   | Damascene NiSi metal gate high-k transistor  |

| US6534224 | 09/772577 | 1/30/2001  | 3/18/2003  | 9  | Phase shift mask and system and method for making the same  |
|-----------|-----------|------------|------------|----|---|
| US6555397 | 09/660723 | 9/13/2000  | 4/29/2003  | 10 | Dry isotropic removal of inorganic anti-<br>reflective coating after poly gate etching                                    |
| US6560764 | 09/624494 | 7/24/2000  | 5/6/2003   | 11 | Dynamic pulse width programming of programmable logic devices   |
| US6579788 | 09/664238 | 9/18/2000  | 6/17/2003  | 12 | Method of forming conductive interconnections on an integrated circuit device   |
| US6603206 | 10/105509 | 3/26/2002  | 8/5/2003   |    | Slot via filled dual damascene interconnect structure without middle etch stop layer                                      |
| US6649426 | 09/893824 | 6/28/2001  | 11/18/2003 | 13 | System and method for active control of spacer deposition   |
| US6656019 | 09/668142 | 9/25/2000  | 12/2/2003  | 14 | Grooved polishing pads and methods of use   |
| US6685548 | 10/424840 | 4/29/2003  | 2/3/2004   |    | Grooved polishing pads and methods of use   |
| US6686668 | 09/764833 | 1/17/2001  | 2/3/2004   | 15 | Structure and method of forming bitline contacts for a vertical DRAM array using a line bitline contact mask              |
| US6703853 | 09/811501 | 3/19/2001  | 3/9/2004   | 16 | Test contact mechanism  |
| US6712681 | 09/715184 | 11/20/2000 | 3/30/2004  | 17 | Polishing pads with polymer filled fibrous web, and methods for fabricating and using same                                |
| US6714556 | 09/618057 | 7/17/2000  | 3/30/2004  | 18 | In-band management of a stacked group of switches by a single CPU   |
| US6727534 | 10/022847 | 12/20/2001 | 4/27/2004  | 19 | Electrically programmed MOS transistor source/drain series resistance   |
| US6746822 | 10/050484 | 1/16/2002  | 6/8/2004   | 20 | Use of surface coupling agent to improve adhesion   |
| US6756276 | 10/335522 | 12/31/2002 | 6/29/2004  | 21 | Strained silicon MOSFET having improved source/drain extension dopant diffusion resistance and method for its fabrication |
| US6791697 | 10/104675 | 3/21/2002  | 9/14/2004  | 22 | Scatterometry structure with embedded ring oscillator, and methods of using same  |
| US6794620 | 10/039525 | 11/7/2001  | 9/21/2004  | 23 | Feedforward temperature control of device under test  |
| US6798028 | 09/847622 | 5/2/2001   | 9/28/2004  | 24 | Field effect transistor with reduced gate delay and method of fabricating the same  |
| US6812159 | 10/420635 | 4/22/2003  | 11/2/2004  | 25 | Method of forming a low leakage<br>dielectric layer providing an increased<br>capacitive coupling                         |
| US6815997 | 09/829160 | 4/9/2001   | 11/9/2004  | 26 | Field effect transistor square multiplier   |

| US6818358 | 10/016439 | 12/11/2001 | 11/16/2004 |    | Method of extending the areas of clear field phase shift generation   |
|-----------|-----------|------------|------------|----|---|
| US6888944 | 09/777506 | 2/5/2001   | 5/3/2005   | 27 | Method for assigning encryption keys  |
| US6905919 | 10/628913 | 7/29/2003  | 6/14/2005  | 28 | Method of forming a partially depleted silicon on insulator (PDSOI) transistor with a pad lock body extension |
| US6924180 | 10/361934 | 2/10/2003  | 8/2/2005   | 29 | Method of forming a pocket implant region after formation of composite insulator spacers                      |
| US6927104 | 10/662674 | 9/15/2003  | 8/9/2005   | 30 | Method of forming double-gated silicon-on-insulator (SOI) transistors with corner rounding                    |
| US6947563 | 09/789451 | 2/20/2001  | 9/20/2005  |    | Method for assigning encryption keys  |
| US6957404 | 10/328112 | 12/20/2002 | 10/18/2005 | 31 | Model checking with layered localization reduction  |
| US6967715 | 10/310759 | 12/6/2002  | 11/22/2005 | 32 | Method and apparatus for optical film measurements in a controlled environment                                |
| US6982215 | 09/186388 | 11/5/1998  | 1/3/2006   | 33 | N type impurity doping using implantation of P2+ ions or As2+ lons  |
| US6991890 | 10/773930 | 2/6/2004   | 1/31/2006  | 34 | Negative photoresist composition involving non-crosslinking chemistry   |
| US6995376 | 10/604204 | 7/1/2003   | 2/7/2006   | 35 | Silicon-on-insulator latch-up pulse-<br>radiation detector  |
| US6998682 | 11/128010 | 5/12/2005  | 2/14/2006  |    | Method of forming a partially depleted silicon on insulator (PDSOI) transistor with a pad lock body extension |
| US7063931 | 10/753989 | 1/8/2004   | 6/20/2006  | 36 | Positive photoresist composition with a polymer including a fluorosulfonamide group and process for its use   |
| US7064074 | 10/624712 | 7/22/2003  | 6/20/2006  | 37 | Technique for forming contacts for buried doped regions in a semiconductor device                             |
| US7064409 | 10/605885 | 11/4/2003  | 6/20/2006  | 38 | Structure and programming of laser fuse   |
| US7119401 | 10/707722 | 1/7/2004   | 10/10/2006 | 39 | Tunable semiconductor diodes  |
| US7122439 | 10/904582 | 11/17/2004 | 10/17/2006 | 40 | Method of fabricating a bottle trench and a bottle trench capacitor   |
| US7132896 | 10/981155 | 11/4/2004  | 11/7/2006  | 41 | Circuit for minimizing filter capacitance leakage induced jitter in phase locked loops (PPLs)                 |
| US7138701 | 10/605483 | 10/2/2003  | 11/21/2006 | 42 | Electrostatic discharge protection networks for triple well semiconductor devices                             |
| US7141854 | 11/174857 | 7/5/2005   | 11/28/2006 |    | Double-gated silicon-on-insulator (SOI) transistors with corner rounding                                      |

| US7217988 | 10/709905 | 6/4/2004   | 5/15/2007  | 43 | Bipolar transistor with isolation and direct contacts   |
|-----------|-----------|------------|------------|----|---|
| US7240322 | 10/907494 | 4/4/2005   | 7/3/2007   | 44 | Method of adding fabrication monitors to integrated circuit chips                                   |
| US7250667 | 11/306663 | 1/5/2006   | 7/31/2007  | 45 | Selectable open circuit and anti-fuse element   |
| US7263716 | 10/066948 | 2/4/2002   | 8/28/2007  | 46 | Remote management mechanism to prevent illegal system commands                                      |
| US7265018 | 10/711486 | 9/21/2004  | 9/4/2007   | 47 | Method to build self-aligned NPN in advanced BiCMOS technology                                      |
| US7278083 | 10/604141 | 6/27/2003  | 10/2/2007  | 48 | Method and system for optimized instruction fetch to protect against soft and hard errors           |
| US7294869 | 11/308541 | 4/4/2006   | 11/13/2007 | 49 | Silicon germanium emitter   |
| US7323278 | 11/687731 | 3/19/2007  | 1/29/2008  |    | Method of adding fabrication monitors to integrated circuit chips                                   |
| US7326610 | 11/271032 | 11/10/2005 | 2/5/2008   | 50 | Process options of forming silicided metal gates for advanced CMOS devices                          |
| US7340712 | 11/142566 | 6/1/2005   | 3/4/2008   | 51 | System and method for creating a standard cell library for reduced leakage and improved performance |
| US7348641 | 10/711182 | 8/31/2004  | 3/25/2008  | 52 | Structure and method of making double-gated self-aligned finFET having gates of different lengths   |
| US7348657 | 11/425491 | 6/21/2006  | 3/25/2008  |    | Electrostatic discharge protection networks for triple well semiconductor devices                   |
| US7358035 | 11/159946 | 6/23/2005  | 4/15/2008  | 53 | Topcoat compositions and methods of use thereof   |
| US7365412 | 11/279434 | 4/12/2006  | 4/29/2008  | 54 | Vertical parallel plate capacitor using spacer shaped electrodes and method for fabrication thereof |
| US7375413 | 11/420527 | 5/26/2006  | 5/20/2008  | 55 | Trench widening without merging   |
| US7378895 | 10/996312 | 11/23/2004 | 5/27/2008  | 56 | On-chip electrically alterable resistor   |
| US7382162 | 11/181954 | 7/14/2005  | 6/3/2008   | 57 | High-density logic techniques with reduced-stack multi-gate field effect transistors                |
| US7384714 | 10/973526 | 10/25/2004 | 6/10/2008  | 58 | Anti-reflective sidewall coated alternating phase shift mask and fabrication method                 |
| US7384824 | 11/362680 | 2/27/2006  | 6/10/2008  |    | Structure and programming of laser fuse   |
| US7385257 | 11/411280 | 4/26/2006  | 6/10/2008  | 59 | Hybrid orientation SOI substrates, and method for forming the same                                  |
| US7387930 | 11/458120 | 7/18/2006  | 6/17/2008  |    | Method of fabricating a bottle trench and a bottle trench capacitor                                 |

| US7394218 | 11/240833 | 10/3/2005  | 7/1/2008  | 60 | Servo system for a two-dimensional micro-electromechanical system (MEMS)-based scanner and method therefor       |
|-----------|-----------|------------|-----------|----|--|
| US7397081 | 10/905041 | 12/13/2004 | 7/8/2008  | 61 | Sidewall semiconductor transistors   |
| US7402854 | 11/496120 | 7/31/2006  | 7/22/2008 | 62 | Three-dimensional cascaded power distribution in a semiconductor device  |
| US7410090 | 11/409244 | 4/21/2006  | 8/12/2008 | 63 | Conductive bonding material fill techniques  |
| US7419611 | 11/219095 | 9/2/2005   | 9/2/2008  | 64 | Processes and materials for step and flash imprint lithography   |
| US7422983 | 11/064561 | 2/24/2005  | 9/9/2008  | 65 | Ta-TaN selective removal process for integrated device fabrication   |
| US7424691 | 11/279312 | 4/11/2006  | 9/9/2008  | 66 | Method for verifying performance of an array by simulating operation of edge cells in a full array model         |
| US7473593 | 11/275514 | 1/11/2006  | 1/6/2009  | 67 | Semiconductor transistors with expanded top portions of gates  |
| US7485539 | 11/332564 | 1/13/2006  | 2/3/2009  | 68 | Strained semiconductor-on-insulator (sSOI) by a simox method   |
| US7504299 | 10/597432 | 1/30/2004  | 3/17/2009 | 69 | Folded node trench capacitor   |
| US7504301 | 11/536126 | 9/28/2006  | 3/17/2009 | 70 | Stressed field effect transistor and methods for its fabrication   |
| US7514370 | 11/419217 | 5/19/2006  | 4/7/2009  | 71 | Compressive nitride film and method of manufacturing thereof   |
| US7518190 | 11/308408 | 3/22/2006  | 4/14/2009 | 72 | Grounding front-end-of-line structures on a SOI substrate  |
| US7518191 | 12/173280 | 7/15/2008  | 4/14/2009 | 73 | Silicon on insulator devices having body-<br>tied-to-source and methods of making                                |
| US7521377 | 11/329560 | 1/11/2006  | 4/21/2009 | 74 | SiCOH film preparation using precursors with built-in porogen functionality                                      |
| US7521763 | 11/619357 | 1/3/2007   | 4/21/2009 | 75 | Dual stress STI  |
| US7525161 | 11/669902 | 1/31/2007  | 4/28/2009 | 76 | Strained MOS devices using source/drain epitaxy  |
| US7526698 | 11/277306 | 3/23/2006  | 4/28/2009 | 77 | Error detection and correction in semiconductor structures   |
| US7531293 | 11/445326 | 6/2/2006   | 5/12/2009 | 78 | Radiation sensitive self-assembled monolayers and uses thereof   |
| US7531367 | 11/333997 | 1/18/2006  | 5/12/2009 | 79 | Utilizing sidewall spacer features to form magnetic tunnel junctions in an integrated circuit                    |
| US7541288 | 11/683590 | 3/8/2007   | 6/2/2009  | 80 | Methods of forming integrated circuit structures using insulator deposition and insulator gap filling techniques |

| US7541290 | 11/683648 | 3/8/2007   | 6/2/2009  | 81 | Methods of forming mask patterns on semiconductor wafers that compensate for nonuniform center-to-edge etch rates during photolithographic processing |
|-----------|-----------|------------|-----------|----|---|
| US7545667 | 11/393270 | 3/30/2006  | 6/9/2009  | 82 | Programmable via structure for three dimensional integration technology   |
| US7552413 | 12/166811 | 7/2/2008   | 6/23/2009 |    | System and computer program for verifying performance of an array by simulating operation of edge cells in a full array model                         |
| US7556996 | 11/736622 | 4/18/2007  | 7/7/2009  | 83 | Field effect transistor comprising a stressed channel region and method of forming the same   |
| US7560141 | 12/268562 | 11/11/2008 | 7/14/2009 | 84 | Method of positioning patterns from block copolymer self-assembly   |
| US7560798 | 11/276369 | 2/27/2006  | 7/14/2009 | 85 | High performance tapered varactor   |
| US7562284 | 11/212208 | 8/26/2005  | 7/14/2009 | 86 | Apparatus, system, and method for mandatory end to end integrity checking in a storage system   |
| US7566921 | 11/838941 | 8/15/2007  | 7/28/2009 |    | Silicon germanium emitter   |
| US7569475 | 11/560044 | 11/15/2006 | 8/4/2009  | 87 | Interconnect structure having enhanced electromigration reliability and a method of fabricating same  |
| US7572689 | 11/937637 | 11/9/2007  | 8/11/2009 | 88 | Method and structure for reducing induced mechanical stresses   |
| US7575970 | 11/470809 | 9/7/2006   | 8/18/2009 | 89 | Deep trench capacitor through SOI substrate and methods of forming  |
| US7583044 | 12/141121 | 6/18/2008  | 9/1/2009  |    | Servo system for a two-dimensional micro-electromechanical system (MEMS)-based scanner and method therefor  |
| US7583833 | 11/341701 | 1/27/2006  | 9/1/2009  | 90 | Method and apparatus for manufacturing data indexing  |
| US7585759 | 11/382135 | 5/8/2006   | 9/8/2009  | 91 | Technique for efficiently patterning an underbump metallization layer using a dry etch process  |
| US7590901 | 11/419271 | 5/19/2006  | 9/15/2009 | 92 | Apparatus, system, and method for dynamic recovery and restoration from design defects in an integrated circuit                                       |
| US7591902 | 11/615080 | 12/22/2006 | 9/22/2009 | 93 | Recirculation and reuse of dummy dispensed resist   |
| US7592258 | 11/619235 | 1/3/2007   | 9/22/2009 | 94 | Metallization layer of a semiconductor device having differently thick metal lines and a method of forming the same                                   |
| US7595247 | 11/753862 | 5/25/2007  | 9/29/2009 | 95 | Halo-first ultra-thin SOI FET for superior short channel control  |

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| US7598540 | 11/451869 | 6/13/2006  | 10/6/2009  | 96  | High performance CMOS devices comprising gapped dual stressors with dielectric gap fillers, and methods of fabricating the same |
|-----------|-----------|------------|------------|-----|---|
| US7600209 | 11/673298 | 2/9/2007   | 10/6/2009  | 97  | Generating constraint preserving testcases in the presence of dead-end constraints  |
| US7601569 | 11/761568 | 6/12/2007  | 10/13/2009 | 98  | Partially depleted SOI field effect<br>transistor having a metallized source<br>side halo region                                |
| US7601645 | 11/872399 | 10/15/2007 | 10/13/2009 | 99  | Methods for fabricating device features having small dimensions   |
| US7605447 | 11/162780 | 9/22/2005  | 10/20/2009 | 100 | Highly manufacturable SRAM cells in substrates with hybrid crystal orientation  |
| US7615418 | 11/380688 | 4/28/2006  | 11/10/2009 | 101 | High performance stress-enhance<br>MOSFET and method of manufacture   |
| US7615433 | 11/304455 | 12/15/2005 | 11/10/2009 | 102 | Double anneal with improved reliability for dual contact etch stop liner scheme   |
| US7618755 | 11/419852 | 5/23/2006  | 11/17/2009 | 103 | Method and system for automatically detecting exposed substrates having a high probability for defocused exposure fields        |
| US7618891 | 11/415922 | 5/1/2006   | 11/17/2009 | 104 | Method for forming self-aligned metal silicide contacts   |
| US7622389 | 11/411353 | 4/25/2006  | 11/24/2009 | 105 | Selective contact formation using masking and resist patterning techniques  |
| US7630235 | 11/692627 | 3/28/2007  | 12/8/2009  | 106 | Memory cells, memory devices and integrated circuits incorporating the same   |
| US7633106 | 11/164072 | 11/9/2005  | 12/15/2009 | 107 | Light shield for CMOS imager  |
| US7638424 | 11/536730 | 9/29/2006  | 12/29/2009 | 108 | Technique for non-destructive metal delamination monitoring in semiconductor devices  |
| US7642125 | 11/855979 | 9/14/2007  | 1/5/2010   | 109 | Phase change memory cell in via array with self-aligned, self-converged bottom electrode and method for manufacturing           |
| US7645641 | 11/781854 | 7/23/2007  | 1/12/2010  | 110 | Cooling device with a preformed compliant interface   |
| US7646470 | 12/013511 | 1/14/2008  | 1/12/2010  | 111 | Immersion lithographic process using a variable scan speed  |
| US7649243 | 11/556833 | 11/6/2006  | 1/19/2010  | 112 | Semiconductor structures incorporating multiple crystallographic planes and methods for fabrication thereof                     |

| US7651831 | 12/136163 | 6/10/2008  | 1/26/2010 |     | Positive photoresist composition with a polymer including a fluorosulfonamide group and process for its use |
|-----------|-----------|------------|-----------|-----|---|
| US7655388 | 11/028421 | 1/3/2005   | 2/2/2010  | 113 | Mask and method to pattern chromeless phase lithography contact hole  |
| US7655972 | 11/164378 | 11/21/2005 | 2/2/2010  | 114 | Structure and method for MOSFET with reduced extension resistance   |
| US7655983 | 11/757472 | 6/4/2007   | 2/2/2010  | 115 | SOI FET with source-side body doping  |
| US7655994 | 11/259644 | 10/26/2005 | 2/2/2010  | 116 | Low threshold voltage semiconductor device with dual threshold voltage control means                        |
| US7657339 | 11/251604 | 10/14/2005 | 2/2/2010  | 117 | Product-related feedback for process control  |
| US7659170 | 11/620406 | 1/5/2007   | 2/9/2010  | 118 | Method of increasing transistor drive current by recessing an isolation trench                              |
| US7659174 | 11/930230 | 10/31/2007 | 2/9/2010  | 119 | Method to enhance device performance with selective stress relief   |
| US7659534 | 11/833354 | 8/3/2007   | 2/9/2010  | 120 | Programmable via devices with air gap isolation   |
| US7659599 | 12/049258 | 3/14/2008  | 2/9/2010  | 121 | Patterned silicon-on-insulator layers and methods for forming the same                                      |
| US7667263 | 11/672109 | 2/7/2007   | 2/23/2010 | 122 | Semiconductor structure including doped silicon carbon liner layer and method for fabrication thereof       |
| US7669748 | 12/173346 | 7/15/2008  | 3/2/2010  |     | Conductive bonding material fill techniques   |
| US7670938 | 11/381219 | 5/2/2006   | 3/2/2010  | 123 | Methods of forming contact openings   |
| US7673173 | 12/212577 | 9/17/2008  | 3/2/2010  | 124 | System and program for transmitting input/output requests from a first controller to a second controller    |
| US7673195 | 11/866502 | 10/3/2007  | 3/2/2010  | 125 | Circuits and methods for characterizing device variation in electronic memory circuits                      |
| US7674562 | 11/297532 | 12/7/2005  | 3/9/2010  | 126 | Angled-wedge chrome-face wall for intensity balance of alternating phase shift mask                         |
| US7675342 | 12/060889 | 4/2/2008   | 3/9/2010  |     | On-chip electrically alterable resistor   |
| US7682961 | 11/422979 | 6/8/2006   | 3/23/2010 | 127 | Methods of forming solder connections and structure thereof   |
| US7688058 | 12/212247 | 9/17/2008  | 3/30/2010 | 128 | Integrated spectrum analyzer circuits and methods for providing on-chip diagnostics                         |
| US7696025 | 11/867840 | 10/5/2007  | 4/13/2010 |     | Sidewall semiconductor transistors  |

| US7696057 | 11/618974 | 1/2/2007   | 4/13/2010 | 129 | Method for co-alignment of mixed optical and electron beam lithographic fabrication levels   |
|-----------|-----------|------------|-----------|-----|--|
| US7700377 | 11/862345 | 9/27/2007  | 4/20/2010 | 130 | Method for reducing etch-induced process uniformities by omitting deposition of an endpoint detection layer during patterning of stressed overlayers in a semiconductor device |
| US7701037 | 11/831208 | 7/31/2007  | 4/20/2010 | 131 | Orientation-independent multi-layer<br>BEOL capacitor  |
| US7718500 | 11/305584 | 12/16/2005 | 5/18/2010 | 132 | Formation of raised source/drain structures in NFET with embedded SiGe in PFET   |
| US7719079 | 11/624436 | 1/18/2007  | 5/18/2010 | 133 | Chip carrier substrate capacitor and method for fabrication thereof  |
| US7724578 | 11/639865 | 12/15/2006 | 5/25/2010 | 134 | Sensing device for floating body cell memory and method thereof  |
| US7727827 | 11/942400 | 11/19/2007 | 6/1/2010  | 135 | Method of forming a semiconductor structure  |
| US7727856 | 11/615980 | 12/24/2006 | 6/1/2010  | 136 | Selective STI stress relaxation through ion implantation   |
| US7728089 | 12/035462 | 2/22/2008  | 6/1/2010  |     | Topcoat compositions and methods of use thereof  |
| US7729161 | 11/833143 | 8/2/2007   | 6/1/2010  | 137 | Phase change memory with dual word lines and source lines and method of operating same   |
| US7732281 | 11/410695 | 4/24/2006  | 6/8/2010  | 138 | Methods for fabricating dual bit flash memory devices  |
| US7732291 | 11/608591 | 12/8/2006  | 6/8/2010  | 139 | Semiconductor device having stressed etch stop layers of different intrinsic stress in combination with PN junctions of different design in different device regions           |
| US7732798 | 12/178921 | 7/24/2008  | 6/8/2010  |     | Programmable via structure for three dimensional integration technology  |
| US7736841 | 12/233245 | 9/18/2008  | 6/15/2010 | 140 | Reflective film interface to restore transverse magnetic wave contrast in lithographic processing  |
| US7737752 | 11/750267 | 5/17/2007  | 6/15/2010 | 141 | Techniques for integrated circuit clock management   |
| US7741191 | 11/951092 | 12/5/2007  | 6/22/2010 | 142 | Method for preventing the formation of electrical shorts via contact ILD voids   |
| US7745320 | 12/124177 | 5/21/2008  | 6/29/2010 | 143 | Method for reducing silicide defects in integrated circuits  |
| US7751924 | 11/830349 | 7/30/2007  | 7/6/2010  | 144 | C4NP servo controlled solder fill head   |

| US7763476 | 11/672146 | 2/7/2007   | 7/27/2010  | 145 | Test structure for determining characteristics of semiconductor alloys in SOI transistors by x-ray diffraction                                      |
|-----------|-----------|------------|------------|-----|---|
| US7763515 | 11/843358 | 8/22/2007  | 7/27/2010  | 146 | Transistor with embedded silicon/germanium material on a strained semiconductor on insulator substrate  |
| US7764078 | 11/623372 | 1/16/2007  | 7/27/2010  | 147 | Test structure for monitoring leakage currents in a metallization layer   |
| US7772071 | 11/383951 | 5/17/2006  | 8/10/2010  | 148 | Strained channel transistor and method of fabrication thereof   |
| US7776682 | 11/110165 | 4/20/2005  | 8/17/2010  | 149 | Ordered porosity to direct memory element formation   |
| US7781343 | 11/757575 | 6/4/2007   | 8/24/2010  | 150 | Semiconductor substrate having a protection layer at the substrate back side  |
| US7784012 | 11/849908 | 9/4/2007   | 8/24/2010  |     | System and method for creating a standard cell library for use in circuit designs   |
| US7787108 | 11/856799 | 9/18/2007  | 8/31/2010  | 151 | Inline stress evaluation in microstructure devices  |
| US7791057 | 12/107573 | 4/22/2008  | 9/7/2010   | 152 | Memory cell having a buried phase change region and method for fabricating the same   |
| US7795104 | 12/030598 | 2/13/2008  | 9/14/2010  | 153 | Method for fabricating device structures having a variation in electrical conductivity  |
| US7799682 | 11/697890 | 4/9/2007   | 9/21/2010  | 154 | Transistor having a locally provided metal silicide region in contact areas and a method of forming the transistor                                  |
| US7816274 | 12/057072 | 3/27/2008  | 10/19/2010 | 155 | Methods for normalizing strain in a semiconductor device  |
| US7821098 | 12/103000 | 4/15/2008  | 10/26/2010 |     | Trench widening without merging   |
| US7825460 | 11/516208 | 9/6/2006   | 11/2/2010  | 156 | Vertical field effect transistor arrays and methods for fabrication thereof   |
| US7829965 | 10/908601 | 5/18/2005  | 11/9/2010  | 157 | Touching microlens structure for a pixel sensor and method of fabrication   |
| US7831324 | 11/746320 | 5/9/2007   | 11/9/2010  | 158 | Method and system for randomizing wafers in a complex process line  |
| US7833849 | 11/323564 | 12/30/2005 | 11/16/2010 | 159 | Method of fabricating a semiconductor structure including one device region having a metal gate electrode located atop a thinned polygate electrode |
| US7834384 | 12/060922 | 4/2/2008   | 11/16/2010 | 160 | Simultaneous conditioning of a plurality of memory cells through series resistors   |
| US7834425 | 12/115065 | 5/5/2008   | 11/16/2010 |     | Hybrid orientation SOI substrates, and method for forming the same  |

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| US7838384 | 11/970665 | 1/8/2008   | 11/23/2010 | 161 | Structure for symmetrical capacitor  |
|-----------|-----------|------------|------------|-----|--|
| US7843007 | 12/539842 | 8/12/2009  | 11/30/2010 | 162 | Metal high-k transistor having silicon sidewall for reduced parasitic capacitance  |
| US7844931 | 12/032728 | 2/18/2008  | 11/30/2010 | 163 | Method and computer system for optimizing the signal time behavior of an electronic circuit design                                 |
| US7846502 | 12/482583 | 6/11/2009  | 12/7/2010  |     | Method of positioning patterns from block copolymer self-assembly  |
| US7847402 | 11/676522 | 2/20/2007  | 12/7/2010  | 164 | BEOL interconnect structures with improved resistance to stress  |
| US7855135 | 12/539860 | 8/12/2009  | 12/21/2010 |     | Method to reduce parastic capacitance in a metal high dielectric constant (MHK) transistor   |
| US7858500 | 12/062972 | 4/4/2008   | 12/28/2010 |     | Low threshold voltage semiconductor device with dual threshold voltage control means   |
| US7859113 | 11/679483 | 2/27/2007  | 12/28/2010 | 165 | Structure including via having refractory metal collar at copper wire and dielectric layer liner-less interface and related method |
| US7860695 | 12/173070 | 7/15/2008  | 12/28/2010 | 166 | Method of creating a load balanced spatial partitioning of a structured, diffusing system of particles                             |
| US7863186 | 12/334746 | 12/15/2008 | 1/4/2011   | 167 | Fully and uniformly silicided gate structure and method for forming same   |
| US7867862 | 11/855168 | 9/14/2007  | 1/11/2011  | 168 | Semiconductor structure including high voltage device  |
| US7875502 | 12/788521 | 5/27/2010  | 1/25/2011  | 169 | Semiconductor chips with crack stop regions for reducing crack propagation from chip edges/corners                                 |
| US7879732 | 11/959034 | 12/18/2007 | 2/1/2011   | 170 | Thin film etching method and semiconductor device fabrication using same   |
| US7880157 | 12/544089 | 8/19/2009  | 2/1/2011   | 171 | Four-terminal reconfigurable devices   |
| US7880229 | 11/874454 | 10/18/2007 | 2/1/2011   | 172 | Body tie test structure for accurate body effect measurement   |
| US7888780 | 12/688470 | 1/15/2010  | 2/15/2011  |     | Semiconductor structures incorporating multiple crystallographic planes and methods for fabrication thereof                        |
| US7897444 | 12/363239 | 1/30/2009  | 3/1/2011   |     | Strained semiconductor-on-insulator (sSOI) by a simox method   |
| US7910450 | 11/276282 | 2/22/2006  | 3/22/2011  | 173 | Method of fabricating a precision buried resistor  |

| US7911001 | 11/778045 | 7/15/2007  | 3/22/2011 | 174 | Methods for forming self-aligned dual stress liners for CMOS semiconductor devices   |
|-----------|-----------|------------|-----------|-----|--|
| US7919812 | 12/554344 | 9/4/2009   | 4/5/2011  |     | Partially depleted SOI field effect<br>transistor having a metallized source<br>side halo region                             |
| US7932128 | 11/771854 | 6/29/2007  | 4/26/2011 | 175 | Polymeric material, method of forming the polymeric material, and method of forming a thin film using the polymeric material |
| US7932506 | 12/177533 | 7/22/2008  | 4/26/2011 | 176 | Fully self-aligned pore-type memory cell having diode access device  |
| US7934181 | 12/130472 | 5/30/2008  | 4/26/2011 | 177 | Method and apparatus for improving SRAM cell stability by using boosted word lines   |
| US7935593 | 12/366356 | 2/5/2009   | 5/3/2011  | 178 | Stress optimization in dual embedded epitaxially grown semiconductor processing  |
| US7939417 | 12/536636 | 8/6/2009   | 5/10/2011 | 179 | Bipolar transistor and back-gated transistor structure and method  |
| US7951678 | 12/190123 | 8/12/2008  | 5/31/2011 | 180 | Metal-gate high-k reference structure  |
| US7955936 | 12/172756 | 7/14/2008  | 6/7/2011  | 181 | Semiconductor fabrication process including an SiGe rework method  |
| US7955940 | 12/551797 | 9/1/2009   | 6/7/2011  | 182 | Silicon-on-insulator substrate with built-<br>in substrate junction  |
| US7955950 | 11/874565 | 10/18/2007 | 6/7/2011  | 183 | Semiconductor-on-insulator substrate with a diffusion barrier  |
| US7955958 | 12/027675 | 2/7/2008   | 6/7/2011  | 184 | Method for fabrication of polycrystalline diodes for resistive memories  |
| US7960283 | 12/825325 | 6/28/2010  | 6/14/2011 |     | Method for reducing silicide defects in integrated circuits  |
| US7964497 | 12/163172 | 6/27/2008  | 6/21/2011 | 185 | Structure to facilitate plating into high aspect ratio vias  |
| US7964970 | 11/964494 | 12/26/2007 | 6/21/2011 | 186 | Technique for enhancing transistor performance by transistor specific contact design   |
| US7973409 | 11/625576 | 1/22/2007  | 7/5/2011  | 187 | Hybrid interconnect structure for performance improvement and reliability enhancement  |
| US7977203 | 12/544964 | 8/20/2009  | 7/12/2011 |     | Programmable via devices with air gap isolation  |
| US7978509 | 12/759479 | 4/13/2010  | 7/12/2011 |     | Phase change memory with dual word lines and source lines and method of operating same                                       |

| US7981748 | 12/541495 | 8/14/2009  | 7/19/2011  |     | Method for fabricating a vertical field effect transistor array comprising a plurality of semiconductor pillars   |
|-----------|-----------|------------|------------|-----|---|
| US7993997 | 11/865563 | 10/1/2007  | 8/9/2011   | 188 | Poly profile engineering to modulate spacer induced stress for device enhancement   |
| US7999320 | 12/342527 | 12/23/2008 | 8/16/2011  | 189 | SOI radio frequency switch with enhanced signal fidelity and electrical isolation   |
| US8003460 | 12/028895 | 2/11/2008  | 8/23/2011  | 190 | Method of forming a semiconductor structure comprising a formation of at least one sidewall spacer structure  |
| US8008744 | 12/790975 | 5/31/2010  | 8/30/2011  |     | Selective STI stress relaxation through ion implantation  |
| US8018312 | 12/369036 | 2/11/2009  | 9/13/2011  | 191 | Inductor and method of operating an inductor by combining primary and secondary coils with coupling structures  |
| US8030635 | 12/353219 | 1/13/2009  | 10/4/2011  | 192 | Polysilicon plug bipolar transistor for phase change memory   |
| US8030687 | 11/764948 | 6/19/2007  | 10/4/2011  | 193 | Field effect transistor incorporating at least one structure for imparting temperature-dependent strain on the channel region and associated method of forming the transistor |
| US8030971 | 12/102097 | 4/14/2008  | 10/4/2011  |     | High-density logic techniques with reduced-stack multi-gate field effect transistors  |
| US8039338 | 12/397574 | 3/4/2009   | 10/18/2011 | 194 | Method for reducing defects of gate of CMOS devices during cleaning processes by modifying a parasitic PN junction  |
| US8039908 | 12/616389 | 11/11/2009 | 10/18/2011 | 195 | Damascene gate having protected shorting regions  |
| US8053303 | 13/075552 | 3/30/2011  | 11/8/2011  | 196 | SOI body contact using E-DRAM technology  |
| US8053348 | 12/547537 | 8/26/2009  | 11/8/2011  | 197 | Method of forming a semiconductor device using a sacrificial uniform vertical thickness spacer structure  |
| US8053819 | 12/120899 | 5/15/2008  | 11/8/2011  |     | Three-dimensional cascaded power distribution in a semiconductor device   |
| US8054986 | 12/543306 | 8/18/2009  | 11/8/2011  | 198 | Method and apparatus for computer communication using audio signals   |
| US8064247 | 12/488795 | 6/22/2009  | 11/22/2011 | 199 | Rewritable memory device based on segregation/re-absorption   |
| US8086974 | 12/176536 | 7/21/2008  | 12/27/2011 | 200 | Structure for fractional-N phased-lock-<br>loop (PLL) system  |
| US8091614 | 11/558842 | 11/10/2006 | 1/10/2012  | 201 | Air/fluid cooling system  |

| US8098536 | 12/019240 | 1/24/2008  | 1/17/2012 | 202 | Self-repair integrated circuit and repair method  |
|-----------|-----------|------------|-----------|-----|---|
| US8110901 | 12/851232 | 8/5/2010   | 2/7/2012  |     | Vertical field effect transistor arrays including gate electrodes annularly surrounding semiconductor pillars         |
| US8115251 | 11/741898 | 4/30/2007  | 2/14/2012 | 203 | Recessed gate channel with low Vt corner  |
| US8119464 | 12/561638 | 9/17/2009  | 2/21/2012 | 204 | Fabrication of semiconductors with high-K/metal gate electrodes   |
| US8125049 | 12/618830 | 11/16/2009 | 2/28/2012 | 205 | MIM capacitor structure in FEOL and related method  |
| US8129256 | 12/194065 | 8/19/2008  | 3/6/2012  | 206 | 3D integrated circuit device fabrication with precisely controllable substrate removal                                |
| US8129843 | 12/853354 | 8/10/2010  | 3/6/2012  | 207 | Methods to mitigate plasma damage in organosilicate dielectrics using a protective sidewall spacer                    |
| US8138072 | 12/500022 | 7/9/2009   | 3/20/2012 | 208 | Semiconductor structures and methods of manufacture   |
| US8138102 | 12/195524 | 8/21/2008  | 3/20/2012 | 209 | Method of placing a semiconducting nanostructure and semiconductor device including the semiconducting nanostructure  |
| US8138607 | 12/632838 | 12/8/2009  | 3/20/2012 | 210 | Metal fill structures for reducing parasitic capacitance  |
| US8143132 | 12/899333 | 10/6/2010  | 3/27/2012 | 211 | Transistor including a high-K metal gate electrode structure formed on the basis of a simplified spacer regime        |
| US8143612 | 12/621000 | 11/18/2009 | 3/27/2012 |     | Phase change memory cell in via array with self-aligned, self-converged bottom electrode and method for manufacturing |
| US8148214 | 12/360961 | 1/28/2009  | 4/3/2012  |     | Stressed field effect transistor and methods for its fabrication  |
| US8148221 | 12/581207 | 10/19/2009 | 4/3/2012  |     | Double anneal with improved reliability for dual contact etch stop liner scheme                                       |
| US8158003 | 12/547874 | 8/26/2009  | 4/17/2012 | 212 | Precision peak matching in liquid chromatography-mass spectroscopy  |
| US8158461 | 12/490872 | 6/24/2009  | 4/17/2012 | 213 | Continuously referencing signals over multiple layers in laminate packages  |
| US8159015 | 12/686403 | 1/13/2010  | 4/17/2012 | 214 | Method and structure for forming capacitors and memory devices on semiconductor-on-insulator (SOI) substrates         |
| US8159248 | 12/542935 | 8/18/2009  | 4/17/2012 | 215 | Interposer structures and methods of manufacturing the same   |

| US8164188 | 12/624065 | 11/23/2009 | 4/24/2012 |     | Methods of forming solder connections and structure thereof  |
|-----------|-----------|------------|-----------|-----|--|
| US8168449 | 12/612258 | 11/4/2009  | 5/1/2012  | 216 | Template-registered diblock copolymer mask for MRAM device formation   |
| US8170704 | 12/400174 | 3/9/2009   | 5/1/2012  | 217 | Method and system for automatic generation of throughput models for semiconductor tools                              |
| US8173331 | 12/685491 | 1/11/2010  | 5/8/2012  | 218 | Method and apparatus for sub-pellicle defect reduction on photomasks   |
| US8173501 | 12/964136 | 12/9/2010  | 5/8/2012  | 219 | Reduced STI topography in high-K metal gate transistors by using a mask after channel semiconductor alloy deposition |
| US8173541 | 12/542269 | 8/17/2009  | 5/8/2012  |     | Chip carrier substrate including capacitor and method for fabrication thereof  |
| US8174106 | 11/511815 | 8/29/2006  | 5/8/2012  | 220 | Through board stacking of multiple LGA-connected components  |
| US8178386 | 11/855983 | 9/14/2007  | 5/15/2012 | 221 | Phase change memory cell array with self-converged bottom electrode and method for manufacturing                     |
| US8185859 | 11/763781 | 6/15/2007  | 5/22/2012 | 222 | System and method to improve chip yield, reliability and performance   |
| US8188786 | 12/565802 | 9/24/2009  | 5/29/2012 | 223 | Modularized three-dimensional capacitor array  |
| US8198190 | 12/103765 | 4/16/2008  | 6/12/2012 | 224 | Semiconductor device and method for patterning vertical contacts and metal lines in a common etch process            |
| US8227333 | 12/948092 | 11/17/2010 | 7/24/2012 | 225 | Ni plating of a BLM edge for Pb-free C4 undercut control   |
| US8231692 | 12/266329 | 11/6/2008  | 7/31/2012 | 226 | Method for manufacturing an electronic device  |
| US8232151 | 13/167303 | 6/23/2011  | 7/31/2012 | 227 | Structure and method for manufacturing asymmetric devices  |
| US8232599 | 12/683456 | 1/7/2010   | 7/31/2012 | 228 | Bulk substrate FET integrated on CMOS SOI  |
| US8232604 | 12/113510 | 5/1/2008   | 7/31/2012 | 229 | Transistor with high-k dielectric sidewall spacer  |
| US8236610 | 12/471656 | 5/26/2009  | 8/7/2012  | 230 | Forming semiconductor chip connections   |
| US8236710 | 12/899638 | 10/7/2010  | 8/7/2012  | 231 | Technique to create a buried plate in embedded dynamic random access memory device                                   |
| US8237086 | 12/014959 | 1/16/2008  | 8/7/2012  | 232 | Removing material from defective opening in glass mold   |
| US8237144 | 13/252152 | 10/3/2011  | 8/7/2012  |     | Polysilicon plug bipolar transistor for phase change memory  |

| US8241970 | 12/197459 | 8/25/2008  | 8/14/2012  | 233 | CMOS with channel P-FinFET and channel N-FinFET having different crystalline orientations and parallel fins |
|-----------|-----------|------------|------------|-----|---|
| US8242542 | 12/644895 | 12/22/2009 | 8/14/2012  | 234 | Semiconductor switching device employing a quantum dot structure  |
| US8242591 | 12/540510 | 8/13/2009  | 8/14/2012  | 235 | Electrostatic chucking of an insulator handle substrate   |
| US8247271 | 12/200352 | 8/28/2008  | 8/21/2012  | 236 | Formation of alpha particle shields in chip packaging   |
| US8250515 | 12/770420 | 4/29/2010  | 8/21/2012  | 237 | Clock alias for timing analysis of an integrated circuit design   |
| US8252673 | 12/643454 | 12/21/2009 | 8/28/2012  | 238 | Spin-on formulation and method for stripping an ion implanted photoresist                                   |
| US8262961 | 12/055513 | 3/26/2008  | 9/11/2012  | 239 | Aromatic vinyl ether based reverse-tone step and flash imprint lithography                                  |
| US8266556 | 12/849171 | 8/3/2010   | 9/11/2012  | 240 | Fracturing continuous photolithography masks  |
| US8273886 | 12/199607 | 8/27/2008  | 9/25/2012  |     | Radiation sensitive self-assembled monolayers and uses thereof  |
| US8276102 | 12/718567 | 3/5/2010   | 9/25/2012  | 241 | Spatial correlation-based estimation of yield of integrated circuits  |
| US8278745 | 12/543104 | 8/18/2009  | 10/2/2012  |     | Through board stacking of multiple LGA-<br>connected components   |
| US8283623 | 11/927073 | 10/29/2007 | 10/9/2012  | 242 | Robust spectral analyzer for one-<br>dimensional and multi-dimensional data<br>analysis                     |
| US8288222 | 12/582139 | 10/20/2009 | 10/16/2012 | 243 | Application of cluster beam implantation for fabricating threshold voltage adjusted FETs                    |
| US8288825 | 12/780962 | 5/17/2010  | 10/16/2012 |     | Formation of raised source/drain structures in NFET with embedded SiGe in PFET                              |
| US8288923 | 12/557122 | 9/10/2009  | 10/16/2012 | 244 | Piezoelectric based energy supply using independent piezoelectric components                                |
| US8293451 | 12/543003 | 8/18/2009  | 10/23/2012 | 245 | Near-infrared absorbing film compositions   |
| US8293546 | 12/477448 | 6/3/2009   | 10/23/2012 | 246 | Integrated circuit system with sub-<br>geometry removal and method of<br>manufacture thereof                |
| US8293606 | 12/973377 | 12/20/2010 | 10/23/2012 |     | Body tie test structure for accurate body effect measurement  |
| US8298882 | 12/563032 | 9/18/2009  | 10/30/2012 | 247 | Metal gate and high-K dielectric devices with PFET channel SiGe   |
| US8299561 | 12/764244 | 4/21/2010  | 10/30/2012 | 248 | Shielding for high-voltage semiconductor-on-insulator devices   |

| US8304301 | 12/621299 | 11/18/2009 | 11/6/2012  | 249 | Implant free extremely thin semiconductor devices  |
|-----------|-----------|------------|------------|-----|--|
| US8309445 | 12/616861 | 11/12/2009 | 11/13/2012 | 250 | Bi-directional self-aligned FET capacitor  |
| US8328892 | 11/930236 | 10/31/2007 | 12/11/2012 | 251 | Solution for forming polishing slurry, polishing slurry and related methods  |
| US8334195 | 12/556139 | 9/9/2009   | 12/18/2012 | 252 | Pixel sensors of multiple pixel size and methods of implant dose control   |
| US8339803 | 12/630993 | 12/4/2009  | 12/25/2012 | 253 | High-speed ceramic modules with hybrid referencing scheme for improved performance and reduced cost                                  |
| US8343836 | 13/363944 | 2/1/2012   | 1/1/2013   |     | Recessed gate channel with low Vt corner   |
| US8349715 | 12/696417 | 1/29/2010  | 1/8/2013   | 254 | Nanoscale chemical templating with oxygen reactive materials   |
| US8354351 | 12/610630 | 11/2/2009  | 1/15/2013  | 255 | Serial irradiation of a substrate by multiple radiation sources  |
| US8357584 | 12/615796 | 11/10/2009 | 1/22/2013  | 256 | Metal capacitor design for improved reliability and good electrical connection   |
| US8357932 | 12/731469 | 3/25/2010  | 1/22/2013  |     | Test pad structure for reuse of interconnect level masks   |
| US8367485 | 12/551941 | 9/1/2009   | 2/5/2013   | 257 | Embedded silicon germanium n-type filed effect transistor for reduced floating body effect   |
| US8368890 | 12/707962 | 2/18/2010  | 2/5/2013   | 258 | Polarization monitoring reticle design for high numerical aperture lithography systems   |
| US8373239 | 12/795962 | 6/8/2010   | 2/12/2013  | 259 | Structure and method for replacement gate MOSFET with self-aligned contact using sacrificial mandrel dielectric                      |
| US8377722 | 12/703211 | 2/10/2010  | 2/19/2013  | 260 | Methods of forming structures with a focused ion beam for use in atomic force probing and structures for use in atomic force probing |
| US8383443 | 12/780193 | 5/14/2010  | 2/26/2013  | 261 | Non-uniform gate dielectric charge for pixel sensor cells and methods of manufacturing   |
| US8383501 | 13/185055 | 7/18/2011  | 2/26/2013  |     | Vertical field effect transistor arrays and methods for fabrication thereof  |
| US8389300 | 12/753270 | 4/2/2010   | 3/5/2013   | 262 | Controlling ferroelectricity in dielectric films by process induced uniaxial strain  |
| US8395196 | 12/946915 | 11/16/2010 | 3/12/2013  | 263 | Hydrogen barrier liner for ferro-electric random access memory (FRAM) chip   |
| US8410553 | 12/964753 | 12/10/2010 | 4/2/2013   |     | Semiconductor structure including high voltage device  |

| US8413083 | 12/465431 | 5/13/2009  | 4/2/2013  | 264 | Mask system employing substantially circular optical proximity correction target and method of manufacture thereof                       |
|-----------|-----------|------------|-----------|-----|--|
| US8415236 | 12/648309 | 12/29/2009 | 4/9/2013  | 265 | Methods for reducing loading effects during film formation   |
| US8415748 | 12/766468 | 4/23/2010  | 4/9/2013  | 266 | Use of epitaxial Ni silicide   |
| US8420460 | 12/055686 | 3/26/2008  | 4/16/2013 | 267 | Method, structure and design structure for customizing history effects of SOI circuits   |
| US8420468 | 13/220753 | 8/30/2011  | 4/16/2013 |     | Strain-compensated field effect transistor and associated method of forming the transistor   |
| US8421218 | 12/983377 | 1/3/2011   | 4/16/2013 | 268 | Method for direct heat sink attachment   |
| US8426262 | 12/862203 | 8/24/2010  | 4/23/2013 | 269 | Stress adjustment in stressed dielectric materials of semiconductor devices by stress relaxation based on radiation                      |
| US8426278 | 12/797420 | 6/9/2010   | 4/23/2013 | 270 | Semiconductor devices having stressor regions and related fabrication methods  |
| US8426316 | 12/204412 | 9/4/2008   | 4/23/2013 |     | Ta-TaN selective removal process for integrated device fabrication   |
| US8431955 | 12/840689 | 7/21/2010  | 4/30/2013 | 271 | Method and structure for balancing power and performance using fluorine and nitrogen doped substrates                                    |
| US8435878 | 12/754917 | 4/6/2010   | 5/7/2013  | 272 | Field effect transistor device and fabrication   |
| US8436425 | 12/915168 | 10/29/2010 | 5/7/2013  | 273 | SOI semiconductor device comprising substrate diodes having a topography tolerant contact structure                                      |
| US8438509 | 12/621564 | 11/19/2009 | 5/7/2013  | 274 | Automated generation of oxide pillar slot shapes in silicon-on-insulator formation technology  |
| US8440561 | 12/844263 | 7/27/2010  | 5/14/2013 | 275 | Three-dimensional semiconductor device comprising an inter-die connection on the basis of functional molecules                           |
| US8440579 | 13/178587 | 7/8/2011   | 5/14/2013 | 276 | Re-establishing surface characteristics of sensitive low-k dielectrics in microstructure device by using an in situ surface modification |
| US8441042 | 12/561827 | 9/17/2009  | 5/14/2013 | 277 | BEOL compatible FET structure  |
| US8444774 | 12/731369 | 3/25/2010  | 5/21/2013 | 278 | Flux composition and process for use thereof   |
| US8445342 | 12/821507 | 6/23/2010  | 5/21/2013 | 279 | Short channel semiconductor devices with reduced halo diffusion  |

| US8445344 | 12/787461 | 5/26/2010 | 5/21/2013 | 280 | Uniform high-k metal gate stacks by adjusting threshold voltage for sophisticated transistors by diffusing a metal species prior to gate patterning |
|-----------|-----------|-----------|-----------|-----|---|
| US8445377 | 13/229250 | 9/9/2011  | 5/21/2013 | 281 | Mechanically robust metal/low-k interconnects   |
| US8445378 | 12/839455 | 7/20/2010 | 5/21/2013 | 282 | Method of manufacturing a CMOS<br>device including molecular storage<br>elements in a via level   |
| US8445964 | 13/349883 | 1/13/2012 | 5/21/2013 |     | Fabrication of semiconductors with high-K/metal gate electrodes   |
| US8445967 | 13/534462 | 6/27/2012 | 5/21/2013 |     | Semiconductor switching device employing a quantum dot structure  |
| US8448098 | 13/453262 | 4/23/2012 | 5/21/2013 |     | Fracturing continuous photolithography masks  |
| US8450046 | 12/392093 | 2/24/2009 | 5/28/2013 | 283 | Methods for enhancing photolithography patterning   |
| US8450168 | 12/823728 | 6/25/2010 | 5/28/2013 | 284 | Ferro-electric capacitor modules,<br>methods of manufacture and design<br>structures  |
| US8450172 | 12/823660 | 6/25/2010 | 5/28/2013 | 285 | Non-insulating stressed material layers in a contact level of semiconductor devices   |
| US8450197 | 12/962968 | 12/8/2010 | 5/28/2013 | 286 | Contact elements of a semiconductor device formed by electroless plating and excess material removal with reduced sheer forces                      |
| US8450206 | 12/839026 | 7/19/2010 | 5/28/2013 | 287 | Method of forming a semiconductor device including a stress buffer material formed above a low-k metallization system                               |
| US8450779 | 12/719058 | 3/8/2010  | 5/28/2013 | 288 | Graphene based three-dimensional integrated circuit device  |
| US8450822 | 12/564996 | 9/23/2009 | 5/28/2013 | 289 | Thick bond pad for chip with cavity package   |
| US8455420 | 13/535466 | 6/28/2012 | 6/4/2013  |     | Spin-on formulation and method for stripping an ion implanted photoresist   |
| US8456006 | 13/174841 | 7/1/2011  | 6/4/2013  |     | Hybrid interconnect structure for performance improvement and reliability enhancement   |
| US8458641 | 13/031754 | 2/22/2011 | 6/4/2013  | 290 | Method, system, and design structure for making voltage environment consistent for reused sub modules in chip design                                |
| US8464130 | 12/330012 | 12/8/2008 | 6/11/2013 | 291 | Memory device and method thereof  |
| US8470676 | 12/350469 | 1/8/2009  | 6/25/2013 | 292 | Programmable element, and memory device or logic circuit  |

| US8471340 | 12/627343 | 11/30/2009 | 6/25/2013 | 293 | Silicon-on-insulator (SOI) structure configured for reduced harmonics and method of forming the structure             |
|-----------|-----------|------------|-----------|-----|---|
| US8476674 | 13/010009 | 1/20/2011  | 7/2/2013  | 294 | Gate conductor with a diffusion barrier   |
| US8476762 | 13/463879 | 5/4/2012   | 7/2/2013  |     | Ni plating of a BLM edge for Pb-free C4 undercut control  |
| US8481164 | 12/061283 | 4/2/2008   | 7/9/2013  | 295 | Materials having predefined morphologies and methods of formation thereof   |
| US8481374 | 12/914123 | 10/28/2010 | 7/9/2013  | 296 | Semiconductor element comprising a low variation substrate diode  |
| US8481380 | 12/888828 | 9/23/2010  | 7/9/2013  | 297 | Asymmetric wedge JFET, related method and design structure  |
| US8481912 | 13/614930 | 9/13/2012  | 7/9/2013  |     | Robust spectral analyzer for one-<br>dimensional and multi-dimensional data<br>analysis                               |
| US8482009 | 13/093034 | 4/25/2011  | 7/9/2013  |     | Silicon-on-insulator substrate with built-<br>in substrate junction   |
| US8482075 | 13/468270 | 5/10/2012  | 7/9/2013  |     | Structure and method for manufacturing asymmetric devices   |
| US8482076 | 12/560585 | 9/16/2009  | 7/9/2013  | 298 | Method and structure for differential silicide and recessed or raised source/drain to improve field effect transistor |
| US8482101 | 12/488899 | 6/22/2009  | 7/9/2013  | 299 | Bipolar transistor structure and method including emitter-base interface impurity                                     |
| US8482132 | 12/575980 | 10/8/2009  | 7/9/2013  | 300 | Pad bonding employing a self-aligned plated liner for adhesion enhancement  |
| US8486268 | 13/406956 | 2/28/2012  | 7/16/2013 |     | Precision peak matching in liquid chromatography-mass spectroscopy  |
| US8487696 | 13/438230 | 4/3/2012   | 7/16/2013 |     | Modularized three-dimensional capacitor array   |
| US8490037 | 13/280853 | 10/25/2011 | 7/16/2013 | 301 | Method and apparatus for tracking uncertain signals   |
| US8490045 | 13/354715 | 1/20/2012  | 7/16/2013 | 302 | Method and device for selectively adding timing margin in an integrated circuit                                       |
| US8491739 | 12/878297 | 9/9/2010   | 7/23/2013 | 303 | Implementing interleaved-dielectric joining of multi-layer laminates  |
| US8492199 | 13/252424 | 10/4/2011  | 7/23/2013 | 304 | Reworkable underfills for ceramic MCM C4 protection   |
| US8492234 | 12/825791 | 6/29/2010  | 7/23/2013 | 305 | Field effect transistor device  |
| US8492265 | 13/431254 | 3/27/2012  | 7/23/2013 |     | Pad bonding employing a self-aligned plated liner for adhesion enhancement  |
| US8492270 | 12/885665 | 9/20/2010  | 7/23/2013 | 306 | Structure for nano-scale metallization and method for fabricating same  |

| US8492279 | 13/164899 | 6/21/2011  | 7/23/2013 | 307 | Method of controlling critical dimensions of vias in a metallization system of a semiconductor device during silicon-ARC etch                        |
|-----------|-----------|------------|-----------|-----|--|
| US8492816 | 12/685156 | 1/11/2010  | 7/23/2013 | 308 | Deep trench decoupling capacitor   |
| US8492823 | 12/473627 | 5/28/2009  | 7/23/2013 |     | High performance tapered varactor  |
| US8492848 | 13/432716 | 3/28/2012  | 7/23/2013 |     | Application of cluster beam implantation for fabricating threshold voltage adjusted FETs   |
| US8492880 | 13/078305 | 4/1/2011   | 7/23/2013 | 309 | Multilayered low k cap with conformal gap fill and UV stable compressive stress properties   |
| US8492892 | 12/963139 | 12/8/2010  | 7/23/2013 | 310 | Solder bump connections  |
| US8497583 | 12/964448 | 12/9/2010  | 7/30/2013 | 311 | Stress reduction in chip packaging by a stress compensation region formed around the chip  |
| US8501545 | 12/963134 | 12/8/2010  | 8/6/2013  | 312 | Reduction of mechanical stress in metal stacks of sophisticated semiconductor devices during die-substrate soldering by an enhanced cool down regime |
| US8504186 | 13/354883 | 1/20/2012  | 8/6/2013  |     | Method for automatic generation of throughput models for semiconductor tools   |
| US8504971 | 13/355099 | 1/20/2012  | 8/6/2013  |     | Method and device for selectively adding timing margin in an integrated circuit  |
| US8506770 | 12/645583 | 12/23/2009 | 8/13/2013 | 313 | Electrochemical planarization system comprising enhanced electrolyte flow  |
| US8507346 | 12/949148 | 11/18/2010 | 8/13/2013 | 314 | Method of forming a semiconductor device having a cut-way hole to expose a portion of a hardmask layer   |
| US8507953 | 12/956291 | 11/30/2010 | 8/13/2013 | 315 | Body controlled double channel transistor and circuits comprising the same   |
| US8507962 | 12/897230 | 10/4/2010  | 8/13/2013 | 316 | Isolation structures for global shutter imager pixel, methods of manufacture and design structures   |
| US8508053 | 12/964359 | 12/9/2010  | 8/13/2013 | 317 | Chip package including multiple sections for reducing chip package interaction   |
| US8512849 | 11/836253 | 8/9/2007   | 8/20/2013 | 318 | Corrugated interfaces for multilayered interconnects   |
| US8513084 | 12/967268 | 12/14/2010 | 8/20/2013 | 319 | Transistor structure with a sidewall-<br>defined intrinsic base to extrinsic base<br>link-up region and method of forming<br>the transistor          |

| US8513109 | 13/052956 | 3/21/2011  | 8/20/2013 | 320 | Method of manufacturing an interconnect structure for a semiconductor device   |
|-----------|-----------|------------|-----------|-----|--|
| US8513117 | 13/296444 | 11/15/2011 | 8/20/2013 | 321 | Process to remove Ni and Pt residues for NiPtSi applications   |
| US8513122 | 13/759146 | 2/5/2013   | 8/20/2013 |     | Method and structure for differential silicide and recessed or raised source/drain to improve field effect transistor          |
| US8513739 | 13/103197 | 5/9/2011   | 8/20/2013 |     | Metal-gate high-k reference structure  |
| US8513769 | 12/765275 | 4/22/2010  | 8/20/2013 | 322 | Electrical fuses and resistors having sublithographic dimensions   |
| US8515567 | 11/313594 | 12/21/2005 | 8/20/2013 | 323 | Enhanced state estimation based upon information credibility   |
| US8518720 | 12/854995 | 8/12/2010  | 8/27/2013 | 324 | UV irradiance monitoring in semiconductor processing using a temperature dependent signal                                      |
| US8518765 | 13/489244 | 6/5/2012   | 8/27/2013 | 325 | Aqua regia and hydrogen peroxide HCl combination to remove Ni and NiPt residues  |
| US8518766 | 13/536366 | 6/28/2012  | 8/27/2013 | 326 | Method of forming switching device having a molybdenum oxynitride metal gate   |
| US8518782 | 12/963054 | 12/8/2010  | 8/27/2013 | 327 | Semiconductor device including asymmetric lightly doped drain (LDD) region, related method and design structure                |
| US8518784 | 12/648744 | 12/29/2009 | 8/27/2013 | 328 | Adjusting of strain caused in a transistor channel by semiconductor material provided for threshold adjustment                 |
| US8519260 | 12/832375 | 7/8/2010   | 8/27/2013 | 329 | Method to evaluate effectiveness of substrate cleanness and quantity of pin holes in an antireflective coating of a solar cell |
| US8519445 | 13/182455 | 7/14/2011  | 8/27/2013 |     | Poly profile engineering to modulate spacer induced stress for device enhancement  |
| US8519497 | 13/396998 | 2/15/2012  | 8/27/2013 |     | Template-registered diblock copolymer mask for MRAM device formation   |
| US8522173 | 13/590300 | 8/21/2012  | 8/27/2013 |     | Spatial correlation-based estimation of yield of integrated circuits   |
| US8529779 | 12/057565 | 3/28/2008  | 9/10/2013 | 330 | Methods for forming surface features using self-assembling masks   |
| US8530310 | 12/650561 | 12/31/2009 | 9/10/2013 | 331 | Memory cell with improved retention  |
| US8533344 | 11/653975 | 1/17/2007  | 9/10/2013 | 332 | Live connection enhancement for data source interface  |

| US8535991 | 12/688254 | 1/15/2010  | 9/17/2013  | 333 | Methods and systems involving electrically reprogrammable fuses  |
|-----------|-----------|------------|------------|-----|--|
| US8536036 | 12/905711 | 10/15/2010 | 9/17/2013  | 334 | Predoped semiconductor material for a high-K metal gate electrode structure of P- and N-channel transistors              |
| US8536041 | 13/559182 | 7/26/2012  | 9/17/2013  |     | Method for fabricating transistor with high-K dielectric sidewall spacer   |
| US8536069 | 13/612159 | 9/12/2012  | 9/17/2013  |     | Multilayered low k cap with conformal gap fill and UV stable compressive stress properties                               |
| US8540890 | 13/675442 | 11/13/2012 | 9/24/2013  | 335 | Protective treatment for porous materials  |
| US8541273 | 12/888434 | 9/23/2010  | 9/24/2013  | 336 | Dielectric stack   |
| US8541842 | 13/442087 | 4/9/2012   | 9/24/2013  | 337 | High-k transistors with low threshold voltage  |
| US8541885 | 13/107515 | 5/13/2011  | 9/24/2013  |     | Technique for enhancing transistor performance by transistor specific contact design                                     |
| US8542058 | 12/983352 | 1/3/2011   | 9/24/2013  | 338 | Semiconductor device including body connected FETs   |
| US8546062 | 13/301841 | 11/22/2011 | 10/1/2013  | 339 | Self-forming top anti-reflective coating compositions and, photoresist mixtures and method of imaging using same         |
| US8546274 | 12/835967 | 7/14/2010  | 10/1/2013  | 340 | Interlayer dielectric material in a semiconductor device comprising stressed layers with an intermediate buffer material |
| US8551313 | 11/940720 | 11/15/2007 | 10/8/2013  | 341 | Method and apparatus for electroplating on soi and bulk semiconductor wafers   |
| US8555216 | 12/100592 | 4/10/2008  | 10/8/2013  | 342 | Structure for electrically tunable resistor  |
| US8557693 | 12/793046 | 6/3/2010   | 10/15/2013 | 343 | Contact resistivity reduction in transistor devices by deep level impurity formation                                     |
| US8558313 | 13/425681 | 3/21/2012  | 10/15/2013 |     | Bulk substrate FET integrated on CMOS SOI  |
| US8558637 | 12/778130 | 5/12/2010  | 10/15/2013 | 344 | Circuit device with signal line transition element   |
| US8563336 | 12/342430 | 12/23/2008 | 10/22/2013 | 345 | Method for forming thin film resistor and terminal bond pad simultaneously   |
| US8563369 | 13/560340 | 7/27/2012  | 10/22/2013 |     | CMOS with channel P-FinFET and channel N-FinFET having different crystalline orientations and parallel fins              |
| US8563398 | 12/977134 | 12/23/2010 | 10/22/2013 | 346 | Electrically conductive path forming below barrier oxide layer and integrated circuit                                    |

| US8563408 | 13/535528 | 6/28/2012  | 10/22/2013 |     | Spin-on formulation and method for stripping an ion implanted photoresist  |
|-----------|-----------|------------|------------|-----|--|
| US8563446 | 13/474790 | 5/18/2012  | 10/22/2013 |     | Technique to create a buried plate in embedded dynamic random access memory device   |
| US8564066 | 12/818828 | 6/18/2010  | 10/22/2013 | 347 | Interface-free metal gate stack  |
| US8564067 | 13/772402 | 2/21/2013  | 10/22/2013 |     | Silicon-on-insulator (SOI) structure configured for reduced harmonics and method of forming the structure                    |
| US8564113 | 13/444193 | 4/11/2012  | 10/22/2013 |     | Electrostatic chucking of an insulator handle substrate  |
| US8566759 | 12/046750 | 3/12/2008  | 10/22/2013 | 348 | Structure for on chip shielding structure for integrated circuits or devices on a substrate                                  |
| US8569131 | 12/949888 | 11/19/2010 | 10/29/2013 | 349 | Source/drain-to-source/drain recessed strap and methods of manufacture of same   |
| US8569616 | 13/237386 | 9/20/2011  | 10/29/2013 | 350 | Method of concetrating solar energy  |
| US8569803 | 13/572742 | 8/13/2012  | 10/29/2013 |     | BEOL compatible FET structrure   |
| US8572524 | 11/943591 | 11/21/2007 | 10/29/2013 | 351 | Statistical optical proximity correction   |
| US8575008 | 12/873058 | 8/31/2010  | 11/5/2013  | 352 | Post-fabrication self-aligned initialization of integrated devices   |
| US8575655 | 13/431328 | 3/27/2012  | 11/5/2013  | 353 | Method and structure for PMOS devices with high K metal gate integration and SiGe channel engineering                        |
| US8575668 | 13/116416 | 5/26/2011  | 11/5/2013  | 354 | Charge breakdown avoidance for MIM elements in SOI base technology and method  |
| US8583796 | 09/750475 | 12/28/2000 | 11/12/2013 |     | Data source interface enhanced error recovery  |
| US8585465 | 12/969969 | 12/16/2010 | 11/19/2013 | 355 | Planarization of a material system in a semiconductor device by using a non-selective in situ prepared slurry                |
| US8586283 | 13/608409 | 9/10/2012  | 11/19/2013 |     | Near-infrared absorbing film compositions  |
| US8586960 | 12/142239 | 6/19/2008  | 11/19/2013 | 356 | Integrated circuit including vertical diode  |
| US8586971 | 13/050519 | 3/17/2011  | 11/19/2013 |     | Polymeric material, method of forming the polymeric material, and method of forming a thin film using the polymeric material |
| US8587288 | 12/823984 | 6/25/2010  | 11/19/2013 | 357 | Digital interface for fast, inline,<br>statistical characterization of process,<br>MOS device and circuit variations         |
| US8589832 | 11/844397 | 8/24/2007  | 11/19/2013 | 358 | On chip shielding structure for integrated circuits or devices on a substrate and method of shielding                        |

| US8589843 | 13/355065 | 1/20/2012  | 11/19/2013 |     | Method and device for selectively adding timing margin in an integrated circuit  |
|-----------|-----------|------------|------------|-----|--|
| US8595919 | 13/095973 | 4/28/2011  | 12/3/2013  | 359 | Silicon chicklet pedestal  |
| US8597991 | 13/568689 | 8/7/2012   | 12/3/2013  |     | Embedded silicon germanium n-type filed effect transistor for reduced floating body effect                                     |
| US8597993 | 12/048461 | 3/14/2008  | 12/3/2013  | 360 | Electrostatic discharge (ESD) device and method of fabricating   |
| US8598027 | 12/690467 | 1/20/2010  | 12/3/2013  |     | High-K transistors with low threshold voltage  |
| US8599642 | 12/822021 | 6/23/2010  | 12/3/2013  | 361 | Port enable signal generation for gating a memory array device output  |
| US8603303 | 12/723842 | 3/15/2010  | 12/10/2013 | 362 | Nanopore based device for cutting long DNA molecules into fragments  |
| US8603894 | 13/423716 | 3/19/2012  | 12/10/2013 | 363 | Stressed source/drain CMOS and method for forming same   |
| US8603895 | 13/610263 | 9/11/2012  | 12/10/2013 | 364 | Methods of forming isolation structures for semiconductor devices by performing a deposition-etch-deposition sequence          |
| US8604337 | 13/604230 | 9/5/2012   | 12/10/2013 |     | Method to evaluate effectiveness of substrate cleanness and quantity of pin holes in an antireflective coating of a solar cell |
| US8604559 | 13/077216 | 3/31/2011  | 12/10/2013 |     | Method of placing a semiconducting nanostructure and semiconductor device including the semiconducting nanostructure           |
| US8609498 | 13/006148 | 1/13/2011  | 12/17/2013 | 365 | Transistor with embedded Si/Ge material having reduced offset and superior uniformity  |
| US8609505 | 13/359032 | 1/26/2012  | 12/17/2013 |     | Method of forming MIM capacitor structure in FEOL  |
| US8609524 | 12/894469 | 9/30/2010  | 12/17/2013 | 366 | Method for making semiconductor device comprising replacement gate electrode structures with an enhanced diffusion barrier     |
| US8610185 | 13/736505 | 1/8/2013   | 12/17/2013 |     | Non-uniform gate dielectric charge for pixel sensor cells and methods of manufacturing   |
| US8612904 | 13/682771 | 11/21/2012 | 12/17/2013 | 367 | Use of polarization and composite illumination source for advanced optical lithography   |
| US8617786 | 13/026168 | 2/11/2011  | 12/31/2013 | 368 | Poly-oxycarbosilane compositions for use in imprint lithography  |

| US8618581 | 13/365577 | 2/3/2012   | 12/31/2013 | 369 | Nanofludic field effect transistor based on surface charge modulated nanochannel                |
|-----------|-----------|------------|------------|-----|---|
| US8618617 | 13/783526 | 3/4/2013   | 12/31/2013 |     | Field effect transistor device  |
| US8618663 | 11/858636 | 9/20/2007  | 12/31/2013 | 370 | Patternable dielectric film structure with improved lithography and method of fabricating same  |
| US8624204 | 13/658861 | 10/24/2012 | 1/7/2014   |     | Serial irradiation of a substrate by multiple radiation sources                                 |
| US8624395 | 13/400900 | 2/21/2012  | 1/7/2014   | 371 | Redundancy design with electro-<br>migration immunity and method of<br>manufacture              |
| US8626328 | 13/012179 | 1/24/2011  | 1/7/2014   | 372 | Discrete sampling based nonlinear control system  |
| US8629010 | 13/278552 | 10/21/2011 | 1/14/2014  | 373 | Carbon nanotube transistor employing embedded electrodes  |
| US8629501 | 13/370898 | 2/10/2012  | 1/14/2014  | 374 | Stress-generating structure for semiconductor-on-insulator devices                              |
| US8629553 | 13/398505 | 2/16/2012  | 1/14/2014  |     | 3D integrated circuit device fabrication with precisely controllable substrate removal          |
| US8633096 | 12/943987 | 11/11/2010 | 1/21/2014  | 375 | Creating anisotropically diffused junctions in field effect transistor devices                  |
| US8633117 | 13/671186 | 11/7/2012  | 1/21/2014  | 376 | Sputter and surface modification etch processing for metal patterning in integrated circuits    |
| US8633633 | 13/570692 | 8/9/2012   | 1/21/2014  |     | Piezoelectric based energy supply using independent piezoelectric components                    |
| US8634063 | 12/637048 | 12/14/2009 | 1/21/2014  | 377 | Wafer with design printed outside active region and spaced by design tolerance of reticle blind |
| US8635483 | 13/079842 | 4/5/2011   | 1/21/2014  | 378 | Dynamically tune power proxy architectures  |
| US8635575 | 13/471627 | 5/15/2012  | 1/21/2014  |     | System and method to improve chip yield, reliability and performance                            |
| US8636917 | 12/876518 | 9/7/2010   | 1/28/2014  |     | Solution for forming polishing slurry, polishing slurry and related methods                     |
| US8637602 | 12/335575 | 12/16/2008 | 1/28/2014  | 379 | Stabilization of vinyl ether materials  |
| US8637844 | 13/097307 | 4/29/2011  | 1/28/2014  |     | Method for fabrication of crystalline diodes for resistive memories                             |
| US8637871 | 12/939462 | 11/4/2010  | 1/28/2014  | 380 | Asymmetric hetero-structure FET and method of manufacture                                       |
| US8640076 | 12/906707 | 10/18/2010 | 1/28/2014  | 381 | Methodology on developing metal fill as library device and design structure                     |

| US8641877 | 13/570470 | 8/9/2012   | 2/4/2014  |     | Nanopore based device for cutting long DNA molecules into fragments  |
|-----------|-----------|------------|-----------|-----|--|
| US8642420 | 13/219331 | 8/26/2011  | 2/4/2014  | 382 | Fabrication of a semiconductor device with extended epitaxial semiconductor regions  |
| US8642454 | 13/475503 | 5/18/2012  | 2/4/2014  | 383 | Low temperature selective epitaxy of silicon germanium alloys employing cyclic deposit and etch                                  |
| US8643401 | 12/432162 | 4/29/2009  | 2/4/2014  | 384 | Integrated circuit communication system with differential signal and method of manufacture thereof                               |
| US8647945 | 12/959824 | 12/3/2010  | 2/11/2014 | 385 | Method of forming substrate contact for semiconductor on insulator (SOI) substrate   |
| US8647946 | 12/621527 | 11/19/2009 | 2/11/2014 | 386 | Control gate   |
| US8648647 | 13/922854 | 6/20/2013  | 2/11/2014 |     | Determining current of a first FET of body connected FETs  |
| US8652762 | 13/423838 | 3/19/2012  | 2/18/2014 | 387 | Organic graded spin on BARC compositions for high NA lithography   |
| US8652941 | 13/474090 | 5/17/2012  | 2/18/2014 | 388 | Wafer dicing employing edge region underfill removal   |
| US8652969 | 13/281715 | 10/26/2011 | 2/18/2014 | 389 | High aspect ratio and reduced undercut trench etch process for a semiconductor substrate   |
| US8653602 | 12/880085 | 9/11/2010  | 2/18/2014 | 390 | Transistor having replacement metal gate and process for fabricating the same  |
| US8658435 | 13/748038 | 1/23/2013  | 2/25/2014 |     | Hydrogen barrier liner for ferro-electric random access memory (FRAM) chip   |
| US8658461 | 13/566050 | 8/3/2012   | 2/25/2014 | 391 | Self aligned carbide source/drain FET  |
| US8658530 | 13/612240 | 9/12/2012  | 2/25/2014 |     | Method of fabricating an epitaxial Ni silicide film  |
| US8658543 | 13/368055 | 2/7/2012   | 2/25/2014 | 392 | Methods for pFET fabrication using APM solutions   |
| US8660681 | 13/006522 | 1/14/2011  | 2/25/2014 | 393 | Method and system for excursion monitoring in optical lithography processes in micro device fabrication                          |
| US8661664 | 12/838597 | 7/19/2010  | 3/4/2014  | 394 | Techniques for forming narrow copper filled vias having improved conductivity  |
| US8664025 | 13/187076 | 7/20/2011  | 3/4/2014  | 395 | Substrate dicing technique for separating semiconductor dies with reduced area consumption                                       |
| US8664049 | 12/776879 | 5/10/2010  | 3/4/2014  | 396 | Semiconductor element formed in a crystalline substrate material and comprising an embedded in situ doped semiconductor material |

| US8664711 | 14/019508 | 9/5/2013   | 3/4/2014  |     | Dielectric stack  |
|-----------|-----------|------------|-----------|-----|---|
| US8664721 | 13/569741 | 8/8/2012   | 3/4/2014  | 397 | FET with FUSI gate and reduced source/drain contact resistance  |
| US8666529 | 12/869973 | 8/27/2010  | 3/4/2014  | 398 | Controlling non-process of record (POR) process limiting yield (PLY) inspection work  |
| US8668833 | 12/125030 | 5/21/2008  | 3/11/2014 | 399 | Method of forming a nanostructure   |
| US8673723 | 13/761610 | 2/7/2013   | 3/18/2014 | 400 | Methods of forming isolation regions for FinFET semiconductor devices   |
| US8673726 | 13/762445 | 2/8/2013   | 3/18/2014 |     | Transistor structure with a sidewall-defined intrinsic base to extrinsic base link-up region and method of forming the transistor   |
| US8673760 | 13/925200 | 6/24/2013  | 3/18/2014 | 401 | Methods of forming structures on an integrated circuit product  |
| US8673766 | 13/476692 | 5/21/2012  | 3/18/2014 | 402 | Methods of forming copper-based conductive structures by forming a copper-based seed layer having an asdeposited thickness profile and thereafter performing an etching process and electroless copper deposition |
| US8674456 | 13/442090 | 4/9/2012   | 3/18/2014 |     | High-K transistors with low threshold voltage   |
| US8677613 | 12/774223 | 5/20/2010  | 3/25/2014 | 403 | Enhanced modularity in heterogeneous 3D stacks  |
| US8678271 | 11/823056 | 6/26/2007  | 3/25/2014 | 404 | Method for preventing void formation in a solder joint  |
| US8679708 | 13/659236 | 10/24/2012 | 3/25/2014 |     | Polarization monitoring reticle design for high numerical aperture lithography systems  |
| US8679899 | 13/226681 | 9/7/2011   | 3/25/2014 | 405 | Multipath soldered thermal interface between a chip and its heat sink   |
| US8679906 | 12/612035 | 11/4/2009  | 3/25/2014 | 406 | Asymmetric multi-gated transistor and method for forming  |
| US8680617 | 12/574126 | 10/6/2009  | 3/25/2014 | 407 | Split level shallow trench isolation for area efficient body contacts in SOI MOSFETS  |
| US8680871 | 13/869662 | 4/24/2013  | 3/25/2014 | 408 | Alignment correction system and method of use   |
| US8681254 | 13/283819 | 10/28/2011 | 3/25/2014 | 409 | Methods for enhancing quality of pixel sensor image frames for global shutter imaging   |
| US8681310 | 12/958678 | 12/2/2010  | 3/25/2014 | 410 | Mechanical fixture of pellicle to lithographic photomask  |
| US8683264 | 13/080773 | 4/6/2011   | 3/25/2014 | 411 | Processing execution requests within different computing environments   |

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| US8683402 | 13/676174 | 11/14/2012 | 3/25/2014 |     | Clock alias for timing analysis of an integrated circuit design  |
|-----------|-----------|------------|-----------|-----|--|
| US8683413 | 13/621242 | 9/15/2012  | 3/25/2014 |     | Method for making high-speed ceramic modules with hybrid referencing scheme for improved performance and reduced cost  |
| US8685806 | 13/908048 | 6/3/2013   | 4/1/2014  |     | Silicon-on-insulator substrate with built-in substrate junction  |
| US8687170 | 13/414954 | 3/8/2012   | 4/1/2014  | 412 | Asymmetric complementary dipole illuminator  |
| US8687445 | 13/846229 | 3/18/2013  | 4/1/2014  |     | Self-repair integrated circuit and repair method   |
| US8691696 | 13/476860 | 5/21/2012  | 4/8/2014  | 413 | Methods for forming an integrated circuit with straightened recess profile   |
| US8692380 | 13/657797 | 10/22/2012 | 4/8/2014  |     | Integrated circuit system with sub-<br>geometry removal and method of<br>manufacture thereof   |
| US8698244 | 12/634893 | 12/10/2009 | 4/15/2014 | 414 | Silicon-on-insulator (SOI) structure configured for reduced harmonics, design structure and method   |
| US8698245 | 12/967329 | 12/14/2010 | 4/15/2014 | 415 | Partially depleted (PD) semiconductor-<br>on-insulator (SOI) field effect transistor<br>(FET) structure with a gate-to-body<br>tunnel current region for threshold<br>voltage (VT) lowering and method of<br>forming the structure |
| US8703274 | 12/244067 | 10/2/2008  | 4/22/2014 | 416 | Microcavity structure and process  |
| US8703552 | 13/419624 | 3/14/2012  | 4/22/2014 |     | Method and structure for forming capacitors and memory devices on semiconductor-on-insulator (SOI) substrates  |
| US8703620 | 13/564071 | 8/1/2012   | 4/22/2014 | 417 | Methods for PFET fabrication using APM solutions   |
| US8704325 | 13/611423 | 9/12/2012  | 4/22/2014 |     | Pixel sensors of multiple pixel size and methods of implant dose control   |
| US8709882 | 12/683759 | 1/7/2010   | 4/29/2014 | 418 | Method to dynamically tune precision resistance  |
| US8710588 | 13/595025 | 8/27/2012  | 4/29/2014 |     | Implant free extremely thin semiconductor devices  |
| US8712569 | 12/147489 | 6/27/2008  | 4/29/2014 | 419 | System for determining potential lot consolidation during manufacturing  |
| US8713387 | 13/658148 | 10/23/2012 | 4/29/2014 | 420 | Channel marking for chip mark overflow and calibration errors  |
| US8716071 | 13/775570 | 2/25/2013  | 5/6/2014  |     | Methods and systems involving electrically reprogrammable fuses  |

| US8716079 | 12/891403 | 9/27/2010  | 5/6/2014  | 421 | Superior fill conditions in a replacement gate approach by corner rounding based on a sacrificial fill material |
|-----------|-----------|------------|-----------|-----|---|
| US8716102 | 13/584981 | 8/14/2012  | 5/6/2014  | 422 | Methods of forming isolation structures for semiconductor devices by performing a dry chemical removal process  |
| US8716798 | 12/779100 | 5/13/2010  | 5/6/2014  | 423 | Methodology for fabricating isotropically recessed source and drain regions of CMOS transistors                 |
| US8716851 | 13/417879 | 3/12/2012  | 5/6/2014  |     | Continuously referencing signals over multiple layers in laminate packages                                      |
| US8722470 | 14/046316 | 10/4/2013  | 5/13/2014 |     | CMOS with channel p-FinFET and channel n-FinFET having different crystalline orientations and parallel fins     |
| US8722548 | 12/890051 | 9/24/2010  | 5/13/2014 | 424 | Structures and techniques for atomic layer deposition   |
| US8723233 | 14/046340 | 10/4/2013  | 5/13/2014 |     | CMOS with channel P-FinFET and channel N-FinFET having different crystalline orientations and parallel fins     |
| US8725483 | 13/008935 | 1/19/2011  | 5/13/2014 | 425 | Minimizing the maximum required link capacity for three-dimensional interconnect routing                        |
| US8735243 | 11/834641 | 8/6/2007   | 5/27/2014 | 426 | FET device with stabilized threshold modifying material   |
| US8736023 | 13/775369 | 2/25/2013  | 5/27/2014 |     | Field effect transistor device and fabrication  |
| US8736061 | 13/490840 | 6/7/2012   | 5/27/2014 | 427 | Integrated circuits having a continuous active area and methods for fabricating same                            |
| US8736816 | 13/415106 | 3/8/2012   | 5/27/2014 |     | Asymmetric complementary dipole illuminator   |
| US8738167 | 13/398481 | 2/16/2012  | 5/27/2014 |     | 3D integrated circuit device fabrication with precisely controllable substrate removal                          |
| US8739098 | 13/771478 | 2/20/2013  | 5/27/2014 | 428 | EUV mask defect reconstruction and compensation repair  |
| US8741722 | 13/605136 | 9/6/2012   | 6/3/2014  | 429 | Formation of dividers between gate ends of field effect transistor devices                                      |
| US8741725 | 12/943084 | 11/10/2010 | 6/3/2014  | 430 | Butted SOI junction isolation structures and devices and method of fabrication                                  |
| US8741730 | 13/565294 | 8/2/2012   | 6/3/2014  |     | Bi-directional self-aligned FET capacitor   |
| US8741770 | 13/468083 | 5/10/2012  | 6/3/2014  |     | Semiconductor device and method for patterning vertical contacts and metal lines in a common etch process       |

| US8741787 | 12/842548 | 7/23/2010  | 6/3/2014  | 431 | Increased density of low-K dielectric materials in semiconductor devices by applying a UV treatment   |
|-----------|-----------|------------|-----------|-----|---|
| US8742475 | 13/554294 | 7/20/2012  | 6/3/2014  |     | Field effect transistor device and fabrication  |
| US8743586 | 13/364759 | 2/2/2012   | 6/3/2014  | 432 | Method and structure for ultra-high density, high data rate ferroelectric storage disk technology using stabilization by a surface conducting layer |
| US8748281 | 12/907596 | 10/19/2010 | 6/10/2014 | 433 | Enhanced confinement of sensitive materials of a high-K metal gate electrode structure  |
| US8749057 | 13/663836 | 10/30/2012 | 6/10/2014 |     | Methods of forming structures with a focused ion beam for use in atomic force probing and structures for use in atomic force probing                |
| US8749760 | 12/396503 | 3/3/2009   | 6/10/2014 |     | Asymmetric complementary dipole illuminator   |
| US8753917 | 12/967625 | 12/14/2010 | 6/17/2014 | 434 | Method of fabricating photoconductor-<br>on-active pixel device   |
| US8753929 | 13/866162 | 4/19/2013  | 6/17/2014 |     | Structure fabrication method  |
| US8754526 | 13/839020 | 3/15/2013  | 6/17/2014 |     | Hybrid interconnect structure for performance improvement and reliability enhancement   |
| US8758962 | 13/443427 | 4/10/2012  | 6/24/2014 |     | Method and apparatus for sub-pellicle defect reduction on photomasks  |
| US8759200 | 13/135031 | 6/23/2011  | 6/24/2014 | 435 | Methods and apparatus for selective epitaxy of Si-containing materials and substitutionally doped crystalline Si-containing material                |
| US8759415 | 13/564812 | 8/2/2012   | 6/24/2014 |     | Aromatic vinyl ether based reverse-tone step and flash imprint lithography  |
| US8759894 | 11/189765 | 7/27/2005  | 6/24/2014 | 436 | System and method for reducing cross-<br>coupling noise between charge storage<br>elements in a semiconductor device                                |
| US8765542 | 13/765797 | 2/13/2013  | 7/1/2014  | 437 | Methods of forming a semiconductor device while preventing or reducing loss of active area and/or isolation regions                                 |
| US8765613 | 13/281688 | 10/26/2011 | 7/1/2014  | 438 | High selectivity nitride etch process   |
| US8766257 | 13/607674 | 9/8/2012   | 7/1/2014  |     | Test pad structure for reuse of interconnect level masks  |
| US8767411 | 13/469487 | 5/11/2012  | 7/1/2014  |     | Electronic device with aerogel thermal isolation  |
| US8769464 | 13/415372 | 3/8/2012   | 7/1/2014  | 439 | Metal density aware signal routing  |

| US8772102 | 13/455616 | 4/25/2012  | 7/8/2014  | 440 | Methods of forming self-aligned contacts for a semiconductor device formed using replacement gate techniques                     |
|-----------|-----------|------------|-----------|-----|--|
| US8772178 | 11/082156 | 3/16/2005  | 7/8/2014  | 441 | Technique for forming a dielectric interlayer above a structure including closely spaced lines                                   |
| US8772843 | 13/183549 | 7/15/2011  | 7/8/2014  | 442 | Oxide deposition by using a double liner approach for reducing pattern density dependence in sophisticated semiconductor devices |
| US8775981 | 13/770287 | 2/19/2013  | 7/8/2014  | 443 | Correcting for overexposure due to overlapping exposures in lithography  |
| US8776868 | 12/550090 | 8/28/2009  | 7/15/2014 | 444 | Thermal ground plane for cooling a computer  |
| US8778772 | 13/348101 | 1/11/2012  | 7/15/2014 | 445 | Method of forming transistor with increased gate width   |
| US8778792 | 13/758386 | 2/4/2013   | 7/15/2014 |     | Solder bump connections  |
| US8784966 | 11/950453 | 12/5/2007  | 7/22/2014 |     | Method of forming a material having a predefined morphology  |
| US8785287 | 12/803754 | 7/6/2010   | 7/22/2014 | 446 | Method to tune narrow width effect with raised S/D structure   |
| US8786088 | 12/966302 | 12/13/2010 | 7/22/2014 | 447 | Semiconductor device including ultra low-K (ULK) metallization stacks with reduced chip-package interaction                      |
| US8790989 | 13/905556 | 5/30/2013  | 7/29/2014 |     | Modularized three-dimensional capacitor array  |
| US8791372 | 13/426892 | 3/22/2012  | 7/29/2014 | 448 | Reducing impedance discontinuity in packages   |
| US8796041 | 12/549799 | 8/28/2009  | 8/5/2014  | 449 | Pillar-based interconnects for magnetoresistive random access memory   |
| US8796057 | 13/766952 | 2/14/2013  | 8/5/2014  |     | Isolation structures for global shutter imager pixel, methods of manufacture and design structures                               |
| US8796596 | 12/901079 | 10/8/2010  | 8/5/2014  | 450 | Heater and memory cell, memory device and recording head including the heater  |
| US8796771 | 14/053708 | 10/15/2013 | 8/5/2014  |     | Creating anisotropically diffused junctions in field effect transistor devices   |
| US8796773 | 13/539700 | 7/2/2012   | 8/5/2014  |     | Metal gate and high-K dielectric devices with PFET channel SiGe  |
| US8796854 | 13/838956 | 3/15/2013  | 8/5/2014  |     | Hybrid interconnect structure for performance improvement and reliability enhancement  |

| US8800952 | 13/432966 | 3/28/2012  | 8/12/2014 |     | Removing material from defective opening in glass mold and related glass mold for injection molded solder               |
|-----------|-----------|------------|-----------|-----|---|
| US8802357 | 13/326404 | 12/15/2011 | 8/12/2014 | 451 | Method for using a topcoat composition  |
| US8802360 | 13/560012 | 7/27/2012  | 8/12/2014 | 452 | Reticles for use in forming implant masking layers and methods of forming implant masking layers                        |
| US8802497 | 13/432963 | 3/28/2012  | 8/12/2014 |     | Forming semiconductor chip connections  |
| US8803276 | 14/073119 | 11/6/2013  | 8/12/2014 |     | Electrostatic discharge (ESD) device and method of fabricating  |
| US8806445 | 13/429981 | 3/26/2012  | 8/12/2014 | 453 | Thread serialization and disablement tool   |
| US8806740 | 13/095969 | 4/28/2011  | 8/19/2014 |     | Silicon chicklet pedestal   |
| US8808453 | 11/737447 | 4/19/2007  | 8/19/2014 | 454 | System for abating the simultaneous flow of silane and arsine   |
| US8809142 | 13/453165 | 4/23/2012  | 8/19/2014 | 455 | Structure and method to form E-fuse with enhanced current crowding  |
| US8815475 | 13/735470 | 1/7/2013   | 8/26/2014 | 456 | Reticle carrier   |
| US8815729 | 13/783715 | 3/4/2013   | 8/26/2014 |     | Methods of forming structures on an integrated circuit product  |
| US8819860 | 13/920676 | 6/18/2013  | 8/26/2014 | 457 | Device comprising a cantilever and scanning system  |
| US8826095 | 13/041248 | 3/4/2011   | 9/2/2014  | 458 | Method and system for providing an improved store-in cache  |
| US8828521 | 13/912593 | 6/7/2013   | 9/9/2014  |     | Corrugated interfaces for multilayered interconnects  |
| US8828826 | 14/015531 | 8/30/2013  | 9/9/2014  | 459 | Method for manufacturing a transistor device comprising a germanium based channel layer                                 |
| US8828869 | 13/852043 | 3/28/2013  | 9/9/2014  | 460 | Methods of forming masking layers for use in forming integrated circuit products  |
| US8829612 | 12/983477 | 1/3/2011   | 9/9/2014  | 461 | Method of forming asymmetric spacers and methods of fabricating semiconductor device using asymmetric spacers           |
| US8829645 | 12/137640 | 6/12/2008  | 9/9/2014  |     | Structure and method to form e-fuse with enhanced current crowding  |
| US8835229 | 13/749745 | 1/25/2013  | 9/16/2014 | 462 | Chip identification for organic laminate packaging and methods of manufacture   |
| US8841652 | 12/627120 | 11/30/2009 | 9/23/2014 |     | Self aligned carbide source/drain FET   |
| US8846476 | 13/766922 | 2/14/2013  | 9/30/2014 | 463 | Methods of forming multiple N-type semiconductor devices with different threshold voltages on a semiconductor substrate |

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| US8847404 | 13/858198 | 4/8/2013  | 9/30/2014  |     | Three-dimensional semiconductor device comprising an inter-die connection on the basis of functional molecules                                   |
|-----------|-----------|-----------|------------|-----|--|
| US8859398 | 12/749890 | 3/30/2010 | 10/14/2014 | 464 | Enhancing adhesion of interlayer dielectric materials of semiconductor devices by suppressing silicide formation at the substrate edge           |
| US8860111 | 13/445194 | 4/12/2012 | 10/14/2014 |     | Phase change memory cell array with self-converged bottom electrode and method for manufacturing   |
| US8866257 | 14/190514 | 2/26/2014 | 10/21/2014 |     | System involving electrically reprogrammable fuses   |
| US8871635 | 13/466895 | 5/8/2012  | 10/28/2014 | 465 | Integrated circuits and processes for forming integrated circuits having an embedded electrical interconnect within a substrate                  |
| US8872236 | 13/195155 | 8/1/2011  | 10/28/2014 | 466 | Scaling of bipolar transistors   |
| US8877552 | 13/076192 | 3/30/2011 | 11/4/2014  | 467 | Method and apparatus for manufacturing electronic integrated circuit chip  |
| US8877582 | 13/771294 | 2/20/2013 | 11/4/2014  | 468 | Methods of inducing a desired stress in the channel region of a transistor by performing ion implantation/anneal processes on the gate electrode |
| US8877642 | 13/756689 | 2/1/2013  | 11/4/2014  | 469 | Double-pattern gate formation processing with critical dimension control   |
| US8877645 | 13/233064 | 9/15/2011 | 11/4/2014  | 470 | Integrated circuit structure having selectively formed metal cap   |
| US8878300 | 14/030048 | 9/18/2013 | 11/4/2014  | 471 | Semiconductor device including outwardly extending source and drain silicide contact regions and related methods                                 |
| US8879221 | 13/406537 | 2/28/2012 | 11/4/2014  | 472 | ESD protection without latch-up  |
| US8883631 | 13/905271 | 5/30/2013 | 11/11/2014 | 473 | Methods of forming conductive structures using a sacrificial material during a metal hard mask removal process                                   |
| US8884379 | 12/711322 | 2/24/2010 | 11/11/2014 | 474 | Strain engineering in semiconductor devices by using a piezoelectric material  |
| US8884387 | 13/568670 | 8/7/2012  | 11/11/2014 |     | Pillar-based interconnects for magnetoresistive random access memory   |
| US8890112 | 13/557385 | 7/25/2012 | 11/18/2014 |     | Controlling ferroelectricity in dielectric films by process induced uniaxial strain  |
| US8890246 | 13/596410 | 8/28/2012 | 11/18/2014 |     | Shielding for high-voltage semiconductor-on-insulator devices  |

| US8895372 | 13/557501 | 7/25/2012  | 11/25/2014 |     | Graphene based three-dimensional integrated circuit device   |
|-----------|-----------|------------|------------|-----|--|
| US8896138 | 13/749744 | 1/25/2013  | 11/25/2014 |     | Chip identification for organic laminate packaging and methods of manufacture  |
| US8896810 | 12/649212 | 12/29/2009 | 11/25/2014 | 475 | Liquid immersion scanning exposure system using an immersion liquid confined within a lens hood  |
| US8898597 | 13/835339 | 3/15/2013  | 11/25/2014 | 476 | Etch failure prediction based on wafer resist top loss   |
| US8900961 | 12/907186 | 10/19/2010 | 12/2/2014  | 477 | Selective deposition of germanium spacers on nitride   |
| US8906794 | 13/956844 | 8/1/2013   | 12/9/2014  | 478 | Gate silicidation  |
| US8911920 | 13/840790 | 3/15/2013  | 12/16/2014 | 479 | Methods for fabricating EUV masks and methods for fabricating integrated circuits using such EUV masks                                       |
| US8912102 | 12/396441 | 3/2/2009   | 12/16/2014 | 480 | Laser annealing  |
| US8912567 | 12/852995 | 8/9/2010   | 12/16/2014 |     | Strained channel transistor and method of fabrication thereof  |
| US8916467 | 13/116396 | 5/26/2011  | 12/23/2014 |     | SOI radio frequency switch with enhanced signal fidelity and electrical isolation  |
| US8921190 | 12/099175 | 4/8/2008   | 12/30/2014 | 481 | Field effect transistor and method of manufacture  |
| US8928145 | 13/533182 | 6/26/2012  | 1/6/2015   |     | Formation of alpha particle shields in chip packaging  |
| US8932920 | 13/904060 | 5/29/2013  | 1/13/2015  | 482 | Self-aligned gate electrode diffusion barriers   |
| US8933435 | 13/727547 | 12/26/2012 | 1/13/2015  | 483 | Tunneling transistor   |
| US8936978 | 12/955388 | 11/29/2010 | 1/20/2015  | 484 | Multigate structure formed with electroless metal deposition   |
| US8940608 | 13/529898 | 6/21/2012  | 1/27/2015  | 485 | Methods for fabricating integrated circuits with drift regions and replacement gates   |
| US8962430 | 13/907237 | 5/31/2013  | 2/24/2015  | 486 | Method for the formation of a protective dual liner for a shallow trench isolation structure   |
| US8963225 | 14/024820 | 9/12/2013  | 2/24/2015  | 487 | Band engineered semiconductor device and method for manufacturing thereof  |
| US8969966 | 13/866077 | 4/19/2013  | 3/3/2015   | 488 | Defective P-N junction for backgated fully depleted silicon on insulator MOSFET  |
| US8987103 | 12/776674 | 5/10/2010  | 3/24/2015  | 489 | Multi-step deposition of a spacer material for reducing void formation in a dielectric material of a contact level of a semiconductor device |

| US8987144 | 13/198107 | 8/4/2011   | 3/24/2015 | 490 | High-K metal gate electrode structures formed by cap layer removal without sacrificial spacer                   |
|-----------|-----------|------------|-----------|-----|---|
| US8987827 | 13/907690 | 5/31/2013  | 3/24/2015 | 491 | Prevention of faceting in epitaxial source drain transistors  |
| US8993445 | 13/740343 | 1/14/2013  | 3/31/2015 | 492 | Selective removal of gate structure sidewall(s) to facilitate sidewall spacer protection                        |
| US9006705 | 13/914514 | 6/10/2013  | 4/14/2015 | 493 | Device with strained layer for quantum well confinement and method for manufacturing thereof                    |
| US9006835 | 14/074905 | 11/8/2013  | 4/14/2015 |     | Transistor with embedded Si/Ge material having reduced offset and superior uniformity                           |
| US9012277 | 13/346043 | 1/9/2012   | 4/21/2015 | 494 | In situ doping and diffusionless<br>annealing of embedded stressor regions<br>in PMOS and NMOS devices          |
| US9024286 | 14/087183 | 11/22/2013 | 5/5/2015  | 495 | RRAM cell with bottom electrode(s) positioned in a semiconductor substrate                                      |
| US9029217 | 14/592412 | 1/8/2015   | 5/12/2015 |     | Band engineered semiconductor device and method for manufacturing thereof                                       |
| US9034746 | 14/524023 | 10/27/2014 | 5/19/2015 |     | Gate silicidation   |
| US9040369 | 13/752567 | 1/29/2013  | 5/26/2015 |     | Structure and method for replacement gate MOSFET with self-aligned contact using sacrificial mandrel dielectric |
| US9040383 | 13/772993 | 2/21/2013  | 5/26/2015 | 496 | Devices with gate-to-gate isolation structures and methods of manufacture                                       |
| US9041107 | 13/833735 | 3/15/2013  | 5/26/2015 |     | Devices with gate-to-gate isolation structures and methods of manufacture                                       |
| US9043438 | 14/059005 | 10/21/2013 | 5/26/2015 |     | Data source interface enhanced error recovery   |
| US9058417 | 14/457537 | 8/12/2014  | 6/16/2015 |     | Thread serialization and disablement tool   |
| US9059017 | 13/776911 | 2/26/2013  | 6/16/2015 |     | Source/drain-to-source/drain recessed strap and methods of manufacture of same                                  |
| US9059180 | 13/737611 | 1/9/2013   | 6/16/2015 |     | Thick bond pad for chip with cavity package   |
| US9059318 | 12/551286 | 8/31/2009  | 6/16/2015 |     | Stressed source/drain CMOS and method of forming same   |
| US9064702 | 13/956273 | 7/31/2013  | 6/23/2015 | 497 | Method for manufacturing semiconductor devices  |
| US9064794 | 14/073919 | 11/7/2013  | 6/23/2015 |     | Integrated circuit including vertical diode   |
| US9076735 | 14/092217 | 11/27/2013 | 7/7/2015  | 498 | Methods for fabricating integrated circuits using chemical mechanical polishing                                 |

| US9076810 | 14/508011 | 10/7/2014  | 7/7/2015   |     | Scaling of bipolar transistors  |
|-----------|-----------|------------|------------|-----|---|
| US9087813 | 14/174804 | 2/6/2014   | 7/21/2015  |     | Control gate  |
| US9089080 | 13/912591 | 6/7/2013   | 7/21/2015  |     | Corrugated interfaces for multilayered interconnects  |
| US9099327 | 13/568839 | 8/7/2012   | 8/4/2015   |     | Multigate structure formed with electroless metal deposition  |
| US9105718 | 14/224384 | 3/25/2014  | 8/11/2015  |     | Butted SOI junction isolation structures and devices and method of fabrication  |
| US9105722 | 14/486108 | 9/15/2014  | 8/11/2015  | 499 | Tucked active region without dummy poly for performance boost and variation reduction   |
| US9142640 | 14/306864 | 6/17/2014  | 9/22/2015  | 500 | Containment structure for epitaxial growth in non-planar semiconductor structure  |
| US9166023 | 13/964009 | 8/9/2013   | 10/20/2015 | 501 | Bulk finFET semiconductor-on-nothing integration  |
| US9196475 | 14/253906 | 4/16/2014  | 11/24/2015 | 502 | Methods for fabricating integrated circuits including fluorine incorporation  |
| US9196829 | 13/833139 | 3/15/2013  | 11/24/2015 |     | Post-fabrication self-aligned initialization of integrated devices  |
| US9219037 | 13/603008 | 9/4/2012   | 12/22/2015 | 503 | Low k porous SiCOH dielectric and integration with post film formation treatment  |
| US9219078 | 13/865795 | 4/18/2013  | 12/22/2015 |     | Simplified multi-threshold voltage scheme for fully depleted SOI MOSFETs  |
| US9231045 | 13/874200 | 4/30/2013  | 1/5/2016   | 504 | Methods for fabricating integrated circuits with polycrystalline silicon resistor structures using a replacment gate process flow, and the integrated circuits fabricated thereby |
| US9245791 | 14/754190 | 6/29/2015  | 1/26/2016  | 505 | Method for fabricating a contact  |
| US9257557 | 14/282463 | 5/20/2014  | 2/9/2016   | 506 | Semiconductor structure with self-<br>aligned wells and multiple channel<br>materials   |
| US9263582 | 14/502428 | 9/30/2014  | 2/16/2016  |     | Strain engineering in semiconductor devices by using a piezoelectric material   |
| US9269710 | 13/796674 | 3/12/2013  | 2/23/2016  |     | Semiconductor devices having stressor regions and related fabrication methods   |
| US9287345 | 14/013409 | 8/29/2013  | 3/15/2016  |     | Semiconductor structure with thin film resistor and terminal bond pad   |
| US9299665 | 14/519235 | 10/21/2014 | 3/29/2016  |     | Formation of alpha particle shields in chip packaging   |
| US9305999 | 13/778419 | 2/27/2013  | 4/5/2016   |     | Stress-generating structure for semiconductor-on-insulator devices  |
| US9312142 | 14/300705 | 6/10/2014  | 4/12/2016  |     | Chemical mechanical polishing method and apparatus  |

| US9324631 | 13/870411 | 4/25/2013  | 4/26/2016 |     | Semiconductor device including a stress<br>buffer material formed above a low-k<br>metallization system |
|-----------|-----------|------------|-----------|-----|---|
| US9324722 | 14/797757 | 7/13/2015  | 4/26/2016 | 507 | Utilization of block-mask and cut-mask for forming metal routing in an IC device                        |
| US9337338 | 14/820938 | 8/7/2015   | 5/10/2016 |     | Tucked active region without dummy poly for performance boost and variation reduction                   |
| US9343354 | 13/970124 | 8/19/2013  | 5/17/2016 |     | Middle of line structures and methods for fabrication   |
| US9348216 | 14/261687 | 4/25/2014  | 5/24/2016 | 508 | Test pad structure for reuse of interconnect level masks  |
| US9349852 | 14/520445 | 10/22/2014 | 5/24/2016 |     | Method, structure and design structure for customizing history effects of SOI circuits                  |
| US9372392 | 14/325515 | 7/8/2014   | 6/21/2016 |     | Reticles for use in forming implant masking layers and methods of forming implant masking layers        |
| US9373507 | 14/618498 | 2/10/2015  | 6/21/2016 |     | Defective P-N junction for backgated fully depleted silicon on insulator mosfet                         |
| US9373557 | 13/535675 | 6/28/2012  | 6/21/2016 |     | Enhanced modularity in heterogeneous 3D stacks  |
| US9377251 | 14/301623 | 6/11/2014  | 6/28/2016 |     | Thermal ground plane for cooling a computer   |
| US9379198 | 14/494699 | 9/24/2014  | 6/28/2016 |     | Integrated circuit structure having selectively formed metal cap  |
| US9385019 | 13/529264 | 6/21/2012  | 7/5/2016  |     | Overhead substrate handling and storage system  |
| US9385179 | 13/765105 | 2/12/2013  | 7/5/2016  |     | Deep trench decoupling capacitor and methods of forming   |
| US9390989 | 13/535694 | 6/28/2012  | 7/12/2016 |     | Enhanced modularity in heterogeneous 3D stacks  |
| US9391200 | 14/308045 | 6/18/2014  | 7/12/2016 |     | FinFETs having strained channels, and methods of fabricating finFETs having strained channels           |
| US9392690 | 14/177530 | 2/11/2014  | 7/12/2016 |     | Method and structure to improve the conductivity of narrow copper filled vias                           |
| US9397174 | 14/516623 | 10/17/2014 | 7/19/2016 |     | Self-aligned gate electrode diffusion barriers  |
| US9399753 | 14/574995 | 12/18/2014 | 7/26/2016 |     | Aqua regia and hydrogen peroxide HCL combination to remove Ni and NiPt residues                         |
| US9406751 | 14/296818 | 6/5/2014   | 8/2/2016  | 509 | Method for making strained semiconductor device and related methods                                     |

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| US9431540 | 14/288766 | 5/28/2014  | 8/30/2016  | 510 | Method for making a semiconductor device with sidewall spacers for confining epitaxial growth   |
|-----------|-----------|------------|------------|-----|---|
| US9478489 | 14/138881 | 12/23/2013 | 10/25/2016 |     | Semiconductor dies with reduced area consumption  |
| US9478600 | 14/175587 | 2/7/2014   | 10/25/2016 |     | Method of forming substrate contact for semiconductor on insulator (SOI) substrate  |
| US9484248 | 13/219144 | 8/26/2011  | 11/1/2016  |     | Patternable dielectric film structure with improved lithography and method of fabricating same  |
| US9502518 | 14/312418 | 6/23/2014  | 11/22/2016 | 511 | Multi-channel gate-all-around FET   |
| US9515180 | 14/588318 | 12/31/2014 | 12/6/2016  |     | Vertical slit transistor with optimized AC performance  |
| US9583625 | 14/523548 | 10/24/2014 | 2/28/2017  |     | Fin structures and multi-Vt scheme based on tapered fin and method to form  |
| US9601565 | 14/578523 | 12/22/2014 | 3/21/2017  | 512 | Zig-zag trench structure to prevent aspect ratio trapping defect escape   |
| US9613855 | 15/091196 | 4/5/2016   | 4/4/2017   | 513 | Methods of forming MIS contact structures on transistor devices in CMOS applications  |
| US9613906 | 14/311457 | 6/23/2014  | 4/4/2017   | 514 | Integrated circuits including modified liners and methods for fabricating the same  |
| US9620380 | 14/972804 | 12/17/2015 | 4/11/2017  | 515 | Methods for fabricating integrated circuits using self-aligned quadruple patterning   |
| US9627272 | 14/833813 | 8/24/2015  | 4/18/2017  | 516 | Patterning scheme to minimize dry/wets strip induced device degradation   |
| US9633911 | 14/668482 | 3/25/2015  | 4/25/2017  |     | Simplified multi-threshold voltage scheme for fully depleted SOI MOSFETs  |
| US9633942 | 14/939365 | 11/12/2015 | 4/25/2017  | 517 | Conductively doped polymer pattern placement error compensation layer   |
| US9633962 | 14/048483 | 10/8/2013  | 4/25/2017  | 518 | Plug via formation with grid features in the passivation layer  |
| US9634142 | 15/076699 | 3/22/2016  | 4/25/2017  | 519 | Method for improving boron diffusion in a germanium-rich fin through germanium concentration reduction in fin S/D regions by thermal mixing |
| US9639652 | 14/148234 | 1/6/2014   | 5/2/2017   | 520 | Compact model for device/circuit/chip leakage current (IDDQ) calculation including process induced uplift factors                           |
| US9640552 | 14/519596 | 10/21/2014 | 5/2/2017   | 521 | Multi-height fin field effect transistors   |

| US9646838 | 14/293627  | 6/2/2014   | 5/9/2017  | 522 | Method of forming a semiconductor structure including silicided and non-silicided circuit elements  |
|-----------|------------|------------|-----------|-----|---|
| US9646962 | 15/285985  | 10/5/2016  | 5/9/2017  | 523 | Low leakage gate controlled vertical electrostatic discharge protection device integration with a planar FinFET                                   |
| US9647063 | 14/797945  | 7/13/2015  | 5/9/2017  |     | Nanoscale chemical templating with oxygen reactive materials  |
| US9653356 | 14/822340  | 8/10/2015  | 5/16/2017 | 524 | Methods of forming self-aligned device level contact structures   |
| US9653365 | 15/093888  | 4/8/2016   | 5/16/2017 | 525 | Methods for fabricating integrated circuits with low, medium, and/or high voltage transistors on an extremely thin silicon-on-insulator substrate |
| US9653571 | 14/739662  | 6/15/2015  | 5/16/2017 | 526 | Freestanding spacer having sub-<br>lithographic lateral dimension and<br>method of forming same   |
| US9660020 | 14/285774  | 5/23/2014  | 5/23/2017 | 527 | Integrated circuits with laterally diffused metal oxide semiconductor structures and methods for fabricating the same                             |
| US9660083 | 14/560,255 | 12/4/2014  | 5/23/2017 | 600 | LDMOS finFET device and method of manufacture using a trench confined epitaxial growth process  |
| US9673083 | 14/608729  | 1/29/2015  | 6/6/2017  | 528 | Methods of forming fin isolation regions<br>on FinFET semiconductor devices by<br>implantation of an oxidation-retarding<br>material              |
| US9679029 | 12/942011  | 11/8/2010  | 6/13/2017 | 529 | Optimizing storage cloud environments through adaptive statistical modeling   |
| US9685334 | 15/134917  | 4/21/2016  | 6/20/2017 | 530 | Methods of forming semiconductor fin with carbon dopant for diffusion control   |
| US9685370 | 14/574889  | 12/18/2014 | 6/20/2017 | 531 | Titanium tungsten liner used with copper interconnects  |
| US9685529 | 15/189476  | 6/22/2016  | 6/20/2017 | 532 | III-V NFETs including channel barrier layers to reduce band-to-band leakage current   |
| US9691626 | 15/077384  | 3/22/2016  | 6/27/2017 | 533 | Method of forming a pattern for interconnection lines in an integrated circuit wherein the pattern includes gamma and beta block mask portions    |
| US9691664 | 15/170126  | 6/1/2016   | 6/27/2017 | 534 | Dual thick EG oxide integration under aggressive SG fin pitch   |
| US9698262 | 15/072130  | 3/16/2016  | 7/4/2017  | 535 | Vertical fin field-effect semiconductor device  |

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| US9740092 | 14/467489 | 8/25/2014  | 8/22/2017  |     | Model-based generation of dummy features   |
|-----------|-----------|------------|------------|-----|--|
| US9748251 | 15/352102 | 11/15/2016 | 8/29/2017  |     | Methods of forming semiconductor devices using semi-bidirectional patterning   |
| US9748352 | 14/984688 | 12/30/2015 | 8/29/2017  |     | Multi-channel gate-all-around FET  |
| US9761539 | 14/753768 | 6/29/2015  | 9/12/2017  |     | Wafer rigidity with reinforcement structure  |
| US9776270 | 14/043047 | 10/1/2013  | 10/3/2017  |     | Chip joining by induction heating  |
| US9786557 | 15/096818 | 4/12/2016  | 10/10/2017 | 536 | Two-dimensional self-aligned super via integration on self-aligned gate contact  |
| US9793168 | 14/977387 | 12/21/2015 | 10/17/2017 |     | Semiconductor structure with self-<br>aligned wells and multiple channel<br>materials  |
| US9818816 | 13/716693 | 12/17/2012 | 11/14/2017 |     | Metal capacitor design for improved reliability and good electrical connection   |
| US9847415 | 14/523076 | 10/24/2014 | 12/19/2017 |     | Field effect transistor and method of manufacture  |
| US9865564 | 14/624601 | 2/18/2015  | 1/9/2018   | 537 | Laser ashing of polyimide for semiconductor manufacturing  |
| US9887133 | 15/623758 | 6/15/2017  | 2/6/2018   |     | Two-dimensional self-aligned super via integration on self-aligned gate contact  |
| US9892971 | 15/392042 | 12/28/2016 | 2/13/2018  | 538 | Crack prevent and stop for thin glass substrates   |
| US9910124 | 15/015176 | 2/4/2016   | 3/6/2018   |     | Apparatus and method for vector s-<br>parameter measurements   |
| US9917087 | 13/961554 | 8/7/2013   | 3/13/2018  | 539 | Integrated circuits with a partially-<br>depleted region formed over a bulk<br>silicon substrate and methods for<br>fabricating the same |
| US9922883 | 15/180158 | 6/13/2016  | 3/20/2018  |     | Method for making strained semiconductor device and related methods  |
| US9929253 | 15/178853 | 6/10/2016  | 3/27/2018  |     | Method for making a semiconductor device with sidewal spacers for confinig epitaxial growth  |
| US9947532 | 15/425338 | 2/6/2017   | 4/17/2018  |     | Forming zig-zag trench structure to prevent aspect ratio trapping defect escape  |
| US9953872 | 15/699138 | 9/8/2017   | 4/24/2018  |     | Semiconductor structure with self-<br>aligned wells and multiple channel<br>materials  |
| US8146046 | 12/120701 | 2008-05-15 | 3/27/20127 |     | Structures for semiconductor structures with error detection and correction  |
| US8405186 | 12/817249 | 2010-06-17 | 3/26/2013  |     | Transistor structure with a sidewall-defined intrinsic base to extrinsic base link-up region and method of forming the structure         |

| US8815674 | 14/172135 | 2014-02-04 | 8/26/2014 | Methods of forming a semiconductor device   |
|-----------|-----------|------------|-----------|---|
|           |           |            |           | by performing a wet acid etching process    |
|           |           |            |           | while preventing or reducing loss of active |
|           |           |            |           | area and/or isolation regions               |

**END OF EXHIBIT A** 

## **EXHIBIT B**

**LISTED PATENTS (Non-US Patents)** 

| LISTED PATENTS | S (Non-US Patents) | T 1        |         |
|----------------|--------------------|------------|---------|
|                |                    |            |         |
|                |                    |            | Country |
| Document No.   | App Serial Number  | Grant Date | Code    |
| CN100440480    | CN200310118724A    | 12/3/2008  | CN      |
| CN100499130    | CN200480032173A    | 6/10/2009  | CN      |
| CN100504796    | CN200610109133A    | 6/24/2009  | CN      |
| CN100505275    | CN200610143976A    | 6/24/2009  | CN      |
| CN100570884    | CN200610001285A    | 12/16/2009 | CN      |
| CN101140931    | CN200710146550A    | 4/6/2011   | CN      |
| CN101170106    | CN200710181659A    | 6/2/2010   | CN      |
| CN101217143    | CN200810002202A    | 3/2/2011   | CN      |
| CN101226914    | CN200810002917A    | 6/2/2010   | CN      |
| CN101359649    | CN200810144109A    | 6/23/2010  | CN      |
| CN101536176    | CN200780032524A    | 9/21/2011  | CN      |
| CN101573791    | CN200780049143A    | 6/15/2011  | CN      |
| CN101681666    | CN200780046338A    | 7/23/2014  | CN      |
| CN101711411    | CN200880016711A    | 11/6/2013  | CN      |
| CN101730939    | CN200880013012A    | 9/26/2012  | CN      |
| CN101764092    | CN200910221772A    | 4/17/2013  | CN      |
| CN101952964    | CN200980103580A    | 10/3/2012  | CN      |
| CN102326059    | CN201080008167A    | 5/21/2014  | CN      |
| CN102341755    | CN201080010182A    | 8/6/2014   | CN      |
| CN102365735    | CN201080013955A    | 3/19/2014  | CN      |
| CN102412131    | CN201110291111A    | 4/8/2015   | CN      |
| CN102640290    | CN201080054255A    | 6/17/2015  | CN      |
| CN102782856    | CN201180011564A    | 11/25/2015 | CN      |
| CN103098200    | CN201180043465A    | 3/9/2016   | CN      |
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END OF EXHIBIT B

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## **EXHIBIT C**

## **ASSIGNED PATENT APPLICATIONS**

**US** Assigned Patent Applications

None

Non-US Assigned Patent Applications

| 1 ton OS Hosigned | Applications         |            |                 |
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**END OF EXHIBIT C** 

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